

# SCANSTA111 **Enhanced SCAN bridge** Multidrop Addressable IEEE 1149.1 (JTAG) Port **General Description**

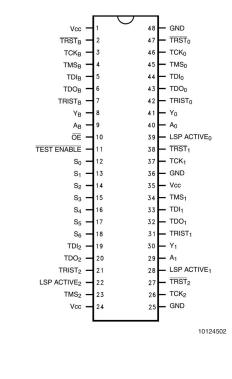
The SCANSTA111 extends the IEEE Std. 1149.1 test bus into a multidrop test bus environment. The advantage of a multidrop approach over a single serial scan chain is improved test throughput and the ability to remove a board from the system and retain test access to the remaining modules. Each SCANSTA111 supports up to 3 local IEEE1149.1 scan rings which can be accessed individually or combined serially. Addressing is accomplished by loading the instruction register with a value matching that of the Slot inputs. Backplane and inter-board testing can easily be accomplished by parking the local TAP Controllers in one of the stable TAP Controller states via a Park instruction. The 32-bit TCK counter enables built in self test operations to be performed on one port while other scan chains are simultaneously tested.

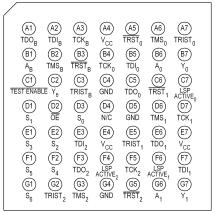
#### Features

- True IEEE 1149.1 hierarchical and multidrop addressable capability
- The 7 slot inputs support up to 121 unique addresses, an Interrogation Address, Broadcast Address, and 4 Multi-cast Group Addresses (address 000000 is reserved)

- 3 IEEE 1149.1-compatible configurable local scan ports
- Mode Register<sub>o</sub> allows local TAPs to be bypassed, selected for insertion into the scan chain individually, or serially in groups of two or three
- Transparent Mode can be enabled with a single instruction to conveniently buffer the backplane IEEE 1149.1 pins to those on a single local scan port
- LSP ACTIVE outputs provide local port enable signals for analog busses supporting IEEE 1149.4.
- General purpose local port passthrough bits are useful for delivering write pulses for FPGA programming or monitoring device status.
- Known Power-up state
- TRST on all local scan ports
- 32-bit TCK counter
- 16-bit LFSR Signature Compactor
- Local TAPs can become TRI-STATE via the OE input to allow an alternate test master to take control of the local TAPs (LSP<sub>0-2</sub> have a TRI-STATE notification output)
- 3.0-3.6V V<sub>CC</sub> Supply Operation
- Power-off high impedance inputs and outputs
- Supports live insertion/withdrawal

# **Connection Diagrams**





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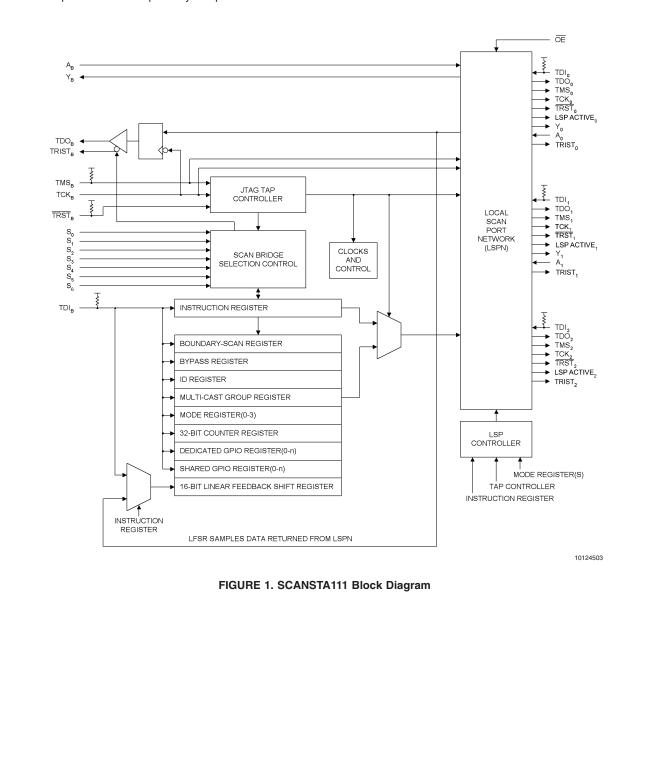
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	TABLE 1. Glossary
LFSR	Linear Feedback Shift Register. When enabled, will generate a 16-bit signature of sampled serial test data.
LSP	Local Scan Port. A four signal port that drives a local (i.e. non-backplane) scan chain. (e.g., TCK <sub>0</sub> , TMS <sub>0</sub> , TDO <sub>0</sub> , TDI <sub>0</sub> ).
Local	Local is used to describe IEEE Std. 1149.1 compliant scan rings and the SCANSTA111 Test Access Port that drives them. The term local was adopted from the system test architecture that the 'STA111 will mos commonly be used in; namely, a system test backplane with a 'STA111 on each card driving up to 3 loca scan rings per card. (Each card can contain multiple 'STA111s, with 3 local scan ports per 'STA111.)
Park/Unpark/Unparked	Parked, unpark, and unparked, are used to describe the state of the LSP controller and the state of the local TAP controllers (the local TAP controllers refers to the TAP controllers of the scan components that make up a local scan ring). Park is also used to describe the action of parking a LSP (transitioning into one of the Parked LSP controller states). It is important to understand that when a LSP controller is in one of the parked states, TMS <sub>n</sub> is held constant, thereby holding or parking the local TAP controllers in a given state.
ТАР	Test Access Port as defined by IEEE Std. 1149.1.
Selected/Unselected	Selected and Unselected refers to the state of the 'STA111 Selection Controller. A selected 'STA111 has been properly addressed and is ready to receive Level 2 protocol. Unselected 'STA111s monitor the system test backplane, but do not accept Level 2 protocol (except for the <i>GOTOWAIT</i> instruction). The data registers and LSPs of unselected 'STA111s are not accessible from the system test master.
Active Scan Chain	The Active Scan Chain refers to the scan chain configuration as seen by the test master at a given moment. When a 'STA111 is selected with all of its LSPs parked, the active scan chain is the current scan register only. When a LSP is unparked, the active scan chain becomes: $\text{TDI}_B \rightarrow$ the current 'STA11 register $\rightarrow$ the local scan ring registers $\rightarrow$ a PAD bit $\rightarrow$ TDO <sub>B</sub> . Refer to <i>Table 7</i> for Unparked configurations of the LSP network.
Level 1 Protocol	Level 1 is the protocol used to address a 'STA111.
Level 2 Protocol	Level 2 is the protocol that is used once a 'STA111 is selected. Level 2 protocol is IEEE Std. 1149.1 compliant when an individual 'STA111 is selected.
PAD	A one bit register that is placed at the end of each local scan port scan-chain. The PAD bit eliminates the prop delay that would be added by the 'STA111 LSPN logic between $TDI_n$ and $TDO_{(n+1)}$ or $TDO_B$ by buffering and synchronizing the LSP TDI inputs to the falling edge of $TCK_B$ , thus allowing data to be scanned at higher frequencies without violating set-up and hold times.
LSB	Least Significant Bit, the right-most position in a register (bit 0).
MSB	Most Significant Bit, the left-most position in a register.

## Architecture

*Figure 1* shows the basic architecture of the 'STA111. The device's major functional blocks are illustrated here. The TAP Controller, a 16-state state machine, is the central control for the device. The instruction register and various test data registers can be scanned to exercise the various functions of the 'STA111 (these registers behave as defined in IEEE Std. 1149.1). The 'STA111 selection controller provides the functionality that allows the 1149.1 protocol to be used in a multi-drop environment. It primarily compares the address

input to the slot identification and enables the 'STA111 for subsequent scan operations. The Local Scan Port Network (LSPN) contains multiplexing logic used to select different port configurations. The LSPN control block contains the Local Scan Port Controllers (LSPC) for each Local Scan Port (LSP<sub>0</sub>, LSP<sub>1</sub> ... LSP<sub>n</sub>). This control block receives input from the 'STA111 instruction register, mode registers, and the TAP controller. Each local port contains all four boundary scan signals needed to interface with the local TAPs plus the optional Test Reset signal (TRST).



Pin Name	No. Pins	I/O	Description		
VCC	3	N/A	Power		
GND	3	N/A	Ground		
TMS <sub>B</sub>	1	I	BACKPLANE TEST MODE SELECT: Controls sequencing through the TAP Controller of the 'STA111. Also controls sequencing of the TAPs which are on the local scan chains. This input has a 25K $\Omega$ pull-up resistor and no ESD clamp diode (ESD is controlled with an alternate method). When the device is power-off (V <sub>DD</sub> floating), this input appears to be a capacitive load to ground (Note 1). When V <sub>DD</sub> = 0V (i.e.; not floating but tied to V <sub>SS</sub> ) this input appears to be a capacitive load with the pull-up to ground.		
TDI <sub>B</sub>	1	I	BACKPLANE TEST DATA INPUT: All backplane scan data is supplied to the 'STA111 thrown this input pin. This input has a $25K\Omega$ pull-up resistor and no ESD clamp diode (ESD is controlled with an alternate method). When the device is power-off (V <sub>DD</sub> floating), this input appears to be a capacitive load to ground (Note 1). When V <sub>DD</sub> = 0V (i.e.; not floating but to V <sub>SS</sub> ) this input appears to be a capacitive load with the pull-up to ground.		
TDO <sub>B</sub>	1	0	BACKPLANE TEST DATA OUTPUT: This output drives test data from the 'STA111 and the local TAPs, back toward the scan master controller. This output has 24mA of drive current. When the device is power-off ( $V_{DD} = 0V$ or floating), this output appears to be a capacitive load (Note 1).		
TCK <sub>B</sub>	1	I	TEST CLOCK INPUT FROM THE BACKPLANE: This is the master clock signal that controls all scan operations of the 'STA111 and of the local scan ports. This input has no pull-up resistor and no ESD clamp diode (ESD is controlled with an alternate method). When the device is power-off ( $V_{DD}$ floating), this input appears to be a capacitive load to ground (Note 1). When $V_{DD} = 0V$ (i.e.; not floating but tied to $V_{SS}$ ) this input appears to be a capacitive load to ground.		
TRST <sub>B</sub>	1	I	TEST RESET: An asynchronous reset signal (active low) which initializes the 'STA111 logic. This input has a $25K\Omega$ pull-up resistor and no ESD clamp diode (ESD is controlled with an alternate method). When the device is power-off (V <sub>DD</sub> floating), this input appears to be a capacitive load to ground (Note 1). When V <sub>DD</sub> = 0V (i.e.; not floating but tied to V <sub>SS</sub> ) this input appears to be a capacitive load with the pull-up to ground.		
TRIST <sub>(B,0-2)</sub>	4	0	TRI-STATE NOTIFICATION OUTPUT: This signal is asserted high when the associated TDC is TRI-STATEd. Associated means $TRIST_B$ is for $TDO_B$ , $TRIST_1$ is for $TDO_1$ , etc. This output has 12mA of drive current.		
A <sub>B</sub>	1	I	BACKPLANE PASS-THROUGH INPUT: A general purpose input which is driven to the $Y_n$ of a single selected LSP. (Not available when multiple LSPs are selected). This input has an internal pull-up resistor.		
Υ <sub>B</sub>	1	0	BACKPLANE PASS-THROUGH OUTPUT: A general purpose output which is driven from the $A_n$ of a single selected LSP. (Not available when multiple LSPs are selected). This output has 24mA of drive current.		
S <sub>(0-6)</sub>	7	Ι	SLOT IDENTIFICATION: The configuration of these pins is used to identify (assign a unique address to) each 'STA111 on the system backplane .		
ŌĒ	1	I	OUTPUT ENABLE for the Local Scan Ports, active low. When high, this active-low control signal TRI-STATEs all local scan ports on the 'STA111, to enable an alternate resource to access one or more of the three local scan chains.		
TDO <sub>(0-2)</sub>	3	0	TEST DATA OUTPUTS: Individual output for each of the local scan ports . These outputs have 24mA of drive current.		
TDI <sub>(0-2)</sub>	3	I	TEST DATA INPUTS: Individual scan data input for each of the local scan ports.		
TMS <sub>(0-2)</sub>	3	0	TEST DATA INPOTS: Individual scan data input for each of the local scan ports. TEST MODE SELECT OUTPUTS: Individual output for each of the local scan ports. TMS <sub>n</sub> does not provide a pull-up resistor (which is assumed to be present on a connected TMS input, per the IEEE 1149.1 requirement). These outputs have 24mA of drive current.		
TCK <sub>(0-2)</sub>	3	0	LOCAL TEST CLOCK OUTPUTS: Individual output for each of the local scan ports. These		

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TABLE 2. Pin Descriptions (Continued)			
Pin Name	No. Pins	I/O	Description
TRST <sub>(0-2)</sub>	3	0	LOCAL TEST RESETS: A gated version of $\overline{\text{TRST}}_{\text{B}}$ . These outputs have 24mA of drive current.
A <sub>(0-1)</sub>	2	I	LOCAL PASS-THROUGH INPUTS: General purpose inputs which can be driven to the backplane pin $Y_B$ . (Only on LSP <sub>0</sub> and LSP <sub>1</sub> . Only available when a single LSP is selected). These inputs have an internal pull-up resistor.
Y <sub>(0-1)</sub>	2	0	LOCAL PASS-THROUGH OUTPUT: General purpose outputs which can be driven from the backplane pin $A_B$ . (Only on LSP <sub>0</sub> and LSP <sub>1</sub> . Only available when a single LSP is selected). These outputs have 24mA of drive current.
LSP_ACTIVE(0-2)	3	0	LOCAL ANALOG TEST BUS ENABLE: These analog pins serve as enable signals for analog busses supporting the IEEE 1149.4 Mixed-Signal Test Bus standard , or for backplane physical layer changes (i.e.; TTL to LVDS). These outputs have 12mA of drive current.
TRIST <sub>(0-2)</sub>	3	0	LOCAL TRI-STATE NOTIFICATION OUTPUTS: This signal is high when the local scan ports are TRI-STATEd . These pins are used for backplane physical layer changes (i.e.; TTL to LVDS). These outputs have 12mA of drive current.
TEST ENABLE	1	I	TEST ENABLE INPUT: This pin is used for factory test and should be tied to $V_{\rm CC}$ for normal operation.

Note 1: Refer to the IBIS model on our website for I/O characteristics.

# **Application Overview**

ADDRESSING SCHEME - The SCANSTA111 architecture extends the functionality of the IEEE 1149.1 Standard by supplementing that protocol with an addressing scheme which allows a test controller to communicate with specific 'STA111s within a network of 'STA111s. That network can include both multi-drop and hierarchical connectivity. In effect, the 'STA111 architecture allows a test controller to dynamically select specific portions of such a network for participation in scan operations. This allows a complex system to be partitioned into smaller blocks for testing purposes. The 'STA111 provides two levels of test-network partitioning capability. First, a test controller can select individual 'STA111s, specific sets of 'STA111s (multi-cast groups), or all 'STA111s (broadcast). This 'STA111-selection process is supported by a Level-1 communication protocol. Second, within each selected 'STA111, a test controller can select one or more of the chip's three local scan-ports. That is, individual local ports can be selected for inclusion in the (single) scan-chain which a 'STA111 presents to the test controller. This mechanism allows a controller to select specific terminal scan-chains within the overall scan network. The port-selection process is supported by a Level-2 protocol.

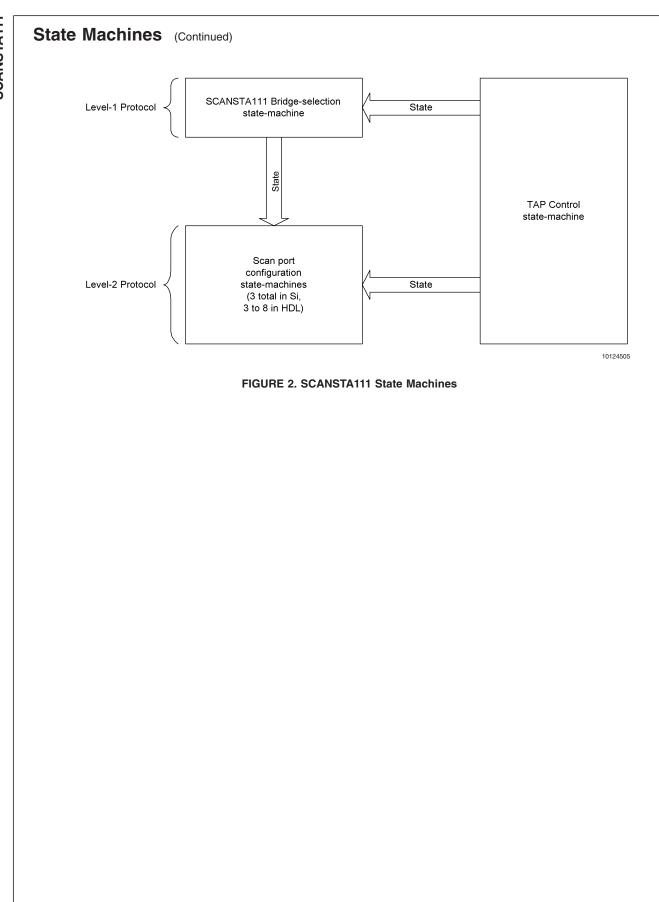
**HIERARCHICAL SUPPORT** - Multiple SCANSTA111's can be used to assemble a hierarchical boundary-scan tree. In such a configuration, the system tester can configure the local ports of a set of 'STA111s so as to connect a specific set of local scan-chains to the active scan chain. Using this capability, the tester can selectively communicate with specific portions of a target system. The tester's scan port is connected to the backplane scan port of a root layer of 'STA111s, each of which can be selected using multi-drop addressing. A second tier of 'STA111s can be connected to this root layer, by connecting a local port (LSP) of a rootlayer 'STA111 to the backplane port of a second-tier 'STA111. This process can be continued to construct a multilevel scan hierarchy. 'STA111 local ports which are not cascaded into higher-level 'STA111s can be thought of as the terminal leaves of a scan tree. The test master can select one or more target leaves by selecting and configuring the local ports of an appropriate set of 'STA111s in the test tree. Check with your ATPG tool vendor to ensure support of this feature.

# **State Machines**

The 'STA111 is IEEE 1149.1-compatible, in that it supports all required 1149.1 operations. In addition, it supports a higher level of protocol, (Level 1), that extends the IEEE 1149.1 Std. to a multi-drop environment.

In multi-drop scan systems, a scan tester can select individual 'STA111s for participation in upcoming scan operations. STA111 selection is accomplished by simultaneously scanning a device address out to multiple STA111s. Through an on-chip address matching process, only those 'STA111s whose statically-assigned address matches the scanned-out address become selected to receive further instructions from the scan tester. STA111 selection is done using a Level-1 protocol, while follow-on instructions are sent to selected 'STA111s by using a Level-2 protocol.

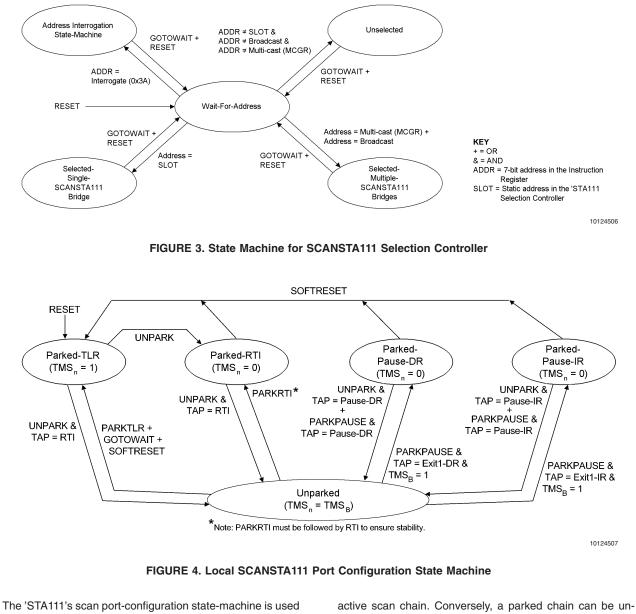




## State Machines (Continued)

The 'STA111 contains three distinct but coupled statemachines (see *Figure 2*). The first of these is the TAP-control state-machine, which is used to drive the 'STA111s scan ports in conformance with the 1149.1 Standard. The second is the 'STA111-selection state-machine (*Figure 3*). The third state-machine actually consists of three identical but independent state-machines (see *Figure 4*), one per 'STA111 local scan port. Each of these scan port selection statemachines allows individual local ports to be inserted into and removed from the 'STA111s overall scan chain. SCANSTA111

The 'STA111 selection state-machine performs the address matching which gives the 'STA111 its multi-drop capability. That logic supports single-'STA111 access, multi-cast, and broadcast. The 'STA111-selection state-machine implements the chip's Level-1 protocol.



to control the insertion of local scan ports into the overall scan chain, or the isolation of local ports from the overall scan chain, or the isolation of local ports from the chain. From the perspective of a system's (single) scan controller, each 'STA111 presents only one scan chain to the master. The 'STA111 architecture allows one or more of the 'STA111's local ports to be included in the active scan chain. Each local port can be parked in one of four stable states (*Parked-TLR, Parked-RTI, Parked-Pause-DR* or *Parked-Pause-IR*), either individually or simultaneously with other local ports. Parking a chain removes that local chain from the

active scan chain. Conversely, a parked chain can be unparked, causing the corresponding local port to be inserted into the active scan chain.

As shown in *Figure 4*, the 'STA111's three scan portconfiguration state-machines allow each of the part's local ports to occupy a different state at any given time. For example, some ports may be parked, perhaps in different states, while other ports participate in scan operations. The state-diagram shows that some state transitions depend on the current state of the TAP-control state-machine. As an example, a local port which is presently in the *Parked-RTI* state does not become unparked (i.e., enter the *Unparked* 

#### State Machines (Continued)

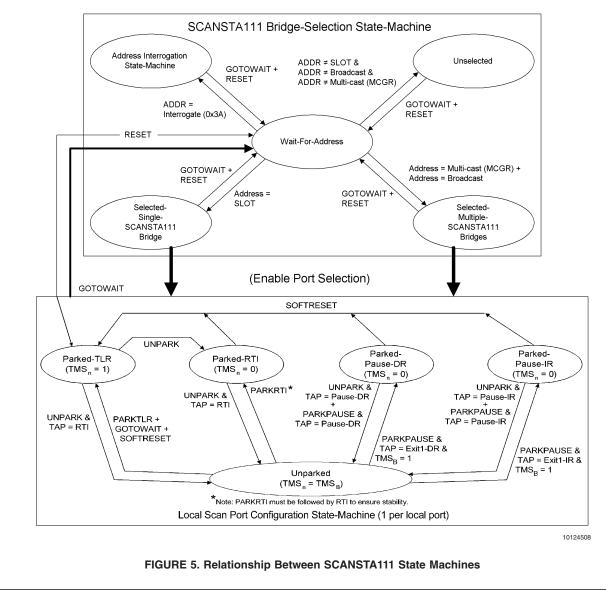
state) until the 'STA111 receives an *UNPARK* instruction and the 'STA111's TAP state-machine enters the *Run-Test/Idle* state.

Similarly, certain transitions of the scan port-configuration state-machine can force the 'STA111's LSP-control state-machine into specific states. For example, when a local port is in the *Unparked* state, the 'STA111 receives the *PARKRTI* instruction and the TAP is transitioned through *Run-Test/Idle* state, the Local Port controller enters the *Parked-RTI* state in which TMS<sub>n</sub> will be held low until the port is later unparked. Once the *Park-RTI* instruction has been updated into the instruction register the TAP MUST be transitioned through the *Run-Test/Idle* state. While TMS<sub>n</sub> is held low, all devices on that local scan chain remain in their current TAP State (the *RTI* TAP controller state in this example).

The 'STA111's scan port-configuration state-machine implements part of the 'STA111's Level-2 protocol. In addition, the 'STA111 provides a number of Level-2 instructions for functions other than local scan port configuration. These instructions provide access to and control of various registers within the 'STA111. This set of instructions includes:

BYPASS	CNTRSEL
EXTEST	LFSRON
SAMPLE/PRELOAD	LFSROFF
IDCODE	CNTRON
MODESEL	CNTROFF
MCGRSEL	GOTOWAIT
LFSRSEL	

*Figure 5* illustrates how the 'STA111's state-machines interact. The 'STA111-selection state-machine enables or disables operation of the chip's three port-selection statemachines. In 'STA111s which are selected via Level-1 protocol (either as individual 'STA111s or as members of broadcast or multi-cast groups), Level-2 protocol commands can be used to park or unpark local scan ports. Note that most transitions of the port-configuration state-machines are gated by particular states of the 'STA111's TAP-control statemachine, as shown in *Figure 4* or *Figure 5*.



#### State Machines (Continued)

Following a hardware reset, the TAP controller statemachine is in the *Test-Logic-Reset* (TLR) state; the 'STA111selection state-machine is in the *Wait-For-Address* state; and each of the three port-selection state-machines is in the *Parked-TLR* state. The 'STA111 is then ready to receive Level-1 protocol, followed by Level-2 protocol.

# **Tester/SCANSTA111 Interface**

An IEEE 1149.1 system tester sends instructions to a 'STA111 via that 'STA111's backplane scan-port. Following test logic reset, the 'STA111's selection state-machine is in the *Wait-For-Address* state. When the 'STA111's TAP controller is sequenced to the *Shift-IR* state, data shifted in through the TDI<sub>B</sub> input is shifted into the 'STA111's instruction register. Note that prior to successful selection of a 'STA111, data is not shifted out of the instruction register and out through the 'STA111's TDO<sub>B</sub> output, as it is during normal scan operations. Instead, as each new bit enters the instruction register's most-significant bit, data shifted out from the least-significant bit is discarded.

When the instruction register is updated with the address data, the 'STA111's address-recognition logic compares the seven least-significant bits of the instruction register with the 7-bit assigned address which is statically present on the  $S_{(0-6)}$  inputs. Simultaneously, the scanned-in address is compared with the reserved Broadcast and Multi-cast addresses. If an address match is detected, the 'STA111-selection state-machine enters one of the two selected states. If the scanned address does not match a valid single-slot addresses or one of the reserved broadcast/multi-cast addresses, the 'STA111-selection state-machine enters the *Unselected* state.

Note that the SLOT inputs should not be set to a value corresponding to a multi-cast group, or to the broadcast address. Also note that the single 'STA111 selection process must be performed for all 'STA111s which are subsequently to be addressed in multi-cast mode. This is required because each such device's Multicast Group Register (MCGR) must be programmed with a multi-cast group number, and the MCGR is not accessible to the test controller until that 'STA111 has first entered the *Selected-Single-'STA111* state.

Once a 'STA111 has been selected, Level-2 protocol is used to issue commands and to access the chip's various registers.

# **Register Set**

The SCANSTA111 includes a number of registers which are used for 'STA111 selection and configuration, scan data manipulation, and scan-support operations. These registers can be grouped as shown in *Table 3*.

The specific fields and functions of each of these registers are detailed in the section of this document titled Data Register Descriptions.

Note that when any of these registers is selected for insertion into the 'STA111's scan-chain, scan data enters through that register's most-significant bit. Similarly, data that is shifted out of the register is fed to the scan input of the next-downstream device in the scan-chain.

Register Name	BSDL Name	Description	
Instruction Register	INSTRUCTION	STA111 addressing and instruction-decode IEEE Std. 1149.1 required	
		register	
Boundary-Scan Register	BOUNDARY	IEEE Std. 1149.1 required register	
Bypass Register	BYPASS	IEEE Std. 1149.1 required register	
Device Identification Register	IDCODE	IEEE Std. 1149.1 optional register	
Multi-Cast Group Register	MCGR	STA111-group address assignment	
Mode Register <sub>o</sub>	MODE	STA111 local-port configuration and control bits	
Mode Register <sub>1</sub>	(TBD)	STA111 local-port configuration and control bits (Note 2)	
Mode Register <sub>2</sub>	(TBD)	STA111 Shared GPIO configuration bits	
Linear-Feedback Shift	LFSR	STA111 scan-data compaction (signature generation)	
Register			
TCK Counter Register	CNTR	Local-port TCK clock-gating (for BIST)	
Dedicated GPIO Register <sub>(0-n)</sub>	(TBD)	STA111 Dedicated GPIO control bits (Note 3)	
Shared GPIO Register(0-n)	(TBD)	STA111 Shared GPIO control bits (Note 3)	

#### **TABLE 3. Register Descriptions**

Note 2: One dedicated and one shared GPIO register exists for each LSP that supports dedicated and/or shared GPIO (maximum of eight shared and eight dedicated GPIO registers).

Note 3: HDL version only

# Level 1 Protocol (Addressing Modes) TABLE 4. SCANSTA111 Address Modes Address Type Hex Address Binary Address TDO<sub>B</sub> State

Hex Address	Binary Address	TDO <sub>B</sub> State
00 to 39,	00000000 to 00111010	Normal IEEE Std. 1149.1
40 to 7F.	01000000 to 01111111	
(80 to FF (Note 4))	(10000000 to 11111111(Note 4))	
3A	00111010	Force strong 0' or weak 1' as ones-complement
		address is shifted out.
3B	00111011	Always TRI-STATED
3C	00111100	Always TRI-STATED
3D	00111101	Always TRI-STATED
3E	00111110	Always TRI-STATED
3F	00111111	Always TRI-STATED
	00 to 39, 40 to 7F. (80 to FF (Note 4)) 3A 3B 3C 3D 3E	00 to 39,         0000000 to 00111010           40 to 7F.         01000000 to 01111111           (80 to FF (Note 4))         (1000000 to 11111111(Note 4))           3A         00111010           3B         00111011           3C         00111100           3D         00111101           3E         00111101

Note 4: Hex addresses 80' to FF' are only available when using the eighth address bit in the HDL version of the SCANSTA111. The Silicon part has seven address lines and will treat the most-significant address bit as a don't care.

The SCANSTA111 supports single and multiple modes of addressing a 'STA111. The single mode selects one 'STA111 and is called Direct Addressing. More than one 'STA111 device can be selected via the Broadcast and Multi-Cast Addressing modes.

**DIRECT ADDRESSING:** The 'STA111 enters the *Wait-For- Address* state when:

- 1. its TAP Controller enters the Test-Logic-Reset state, or
- 2. its instruction register is updated with the *GOTOWAIT* instruction (while either selected or unselected).

Each 'STA111 within a scan network must be statically configured with a unique address via its  $S_{(0-6)}$  inputs. While the 'STA111 controller is in the *Wait-For-Address* state, data shifted into bits 6 through 0 of the instruction register is compared with the address present on the  $S_{(0-6)}$  inputs in the *Update-IR* state. If the seven (7) LSBs of the instruction register match the address on the  $S_{(0-6)}$  inputs, (see *Figure* 6) the 'STA111 becomes selected, and is ready to receive Level 2 Protocol (i.e., further instructions). When the 'STA111 is selected, its device identification register is inserted into the active scan chain.

All 'STA111s whose  $S_{(0-6)}$  address does not match the instruction register address become unselected. They will remain unselected until either their TAP Controller enters the

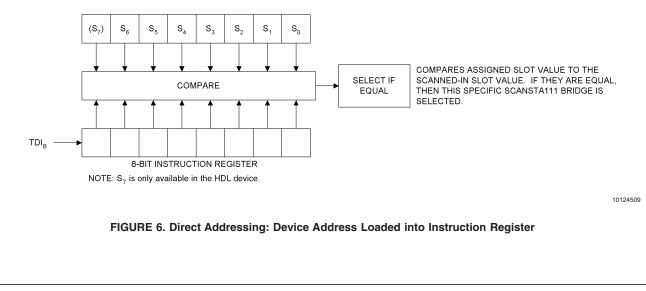
*Test-Logic-Reset* state, or their instruction register is updated with the *GOTOWAIT* instruction.

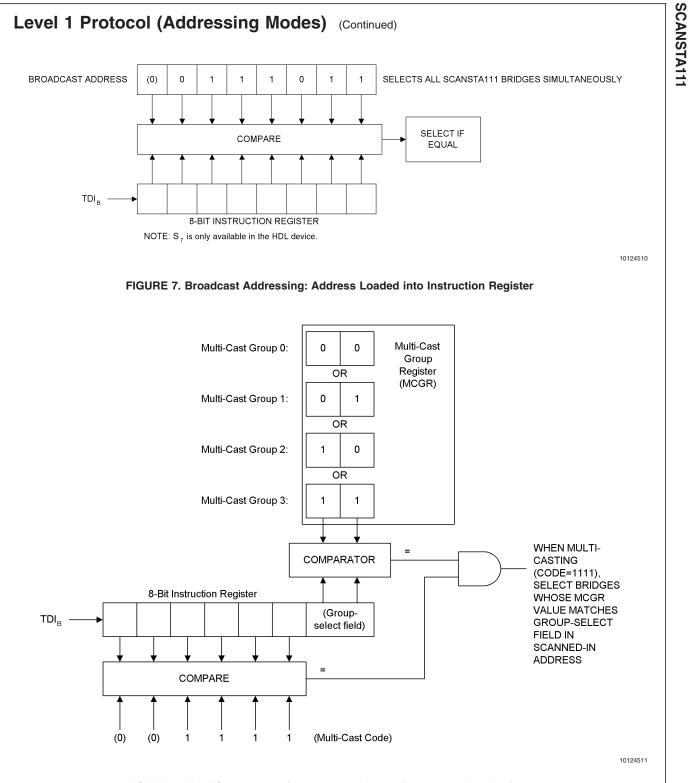
#### BROADCAST ADDRESSING:

The Broadcast Address allows a tester to simultaneously select all 'STA111s in a test network. This mode is useful in testing systems which contain multiple identical boards. To avoid bus contention between scan-path output drivers on different boards, each 'STA111's  $TDO_B$  buffer is always TRI-STATEd while in Broadcast mode. In this configuration, the on-chip Linear Feedback Shift Register (LFSR) can be used to accumulate a test result signature for each board that can be read back later by direct-addressing each board's 'STA111.

#### **MULTICAST ADDRESSING:**

As a way to make the broadcast mechanism more selective, the 'STA111 provides a Multi-cast addressing mode. A 'STA111's multi-cast group register (MCGR) can be programmed to assign that 'STA111 to one of four (4) Multi-Cast groups. When 'STA111s in the *Wait-For-Address* state are updated with a Multi-Cast address, all 'STA111s whose MCGR matches the Multi-Cast group will become selected. As in Broadcast mode, TDO<sub>B</sub> is always TRI-STATEd while in Multi-cast mode.







# Level 2 Protocol

Once the SCANSTA111 has been successfully addressed and selected, its internal registers may be accessed via Level-2 Protocol. Level-2 Protocol is compliant to IEEE Std. 1149.1 TAP protocol with one exception: if the 'STA111 is selected via the Broadcast or Multi-Cast address, TDO<sub>B</sub> is always TRI-STATED. (The TDO<sub>B</sub> buffer must be implemented this way to prevent bus contention.) Upon being selected, (i.e., the 'STA111 Selection controller transitions from the *Wait-For-Address* state to one of the Selected states), each of the local scan ports ( $LSP_0$ ,  $LSP_1$ ,  $LSP_2$ ) remains parked in one of the following four TAP Controller states: *Test-Logic-Reset*, *Run-Test/Idle*, *Pause-DR*, or

# Level 2 Protocol (Continued)

 $\it Pause-IR$  and the active scan chain consists of:  $\rm TDI_B$  through the instruction register (or the IDCODE register) and out through TDO\_B.

 $\text{TDI}_{\text{B}} \rightarrow \text{Instruction Register} \rightarrow \text{TDO}_{\text{B}}$ 

The UNPARK instruction (described later) is used to insert one or more local scan ports into the active scan chain. *Table 7* describes which local ports are inserted into the chain, and in what order.

**LEVEL 2 INSTRUCTION TYPES** There are two types of instructions (reference *Table 5*):

1. Instructions that insert a 'STA111 register into the active scan chain so that the register can be captured or up-

dated (*BYPASS, SAMPLE/PRELOAD, EXTEST, ID-CODE, MODESEL, MCGRSEL, LFSR-SEL, CNTR-SEL*).

Instructions that configure local ports or control the operation of the linear feedback shift register and counter registers (UNPARK, PARKTRL, PARKRTI, PARK-PAUSE, GOTOWAIT, SOFTRESET, LFSRON, LFS-ROFF, CNTRON, CNTROFF). These instructions, along with any other yet undefined Op-Codes, will cause the device identification register to be inserted into the active scan chain.

TABLE 5. Level 2 Protocol and Op-Codes			
nstructions	Hex Op-Code	Binary Op-Code	Data Register
BYPASS	FF	1111 1111	Bypass Register
EXTEST	00	0000 0000	Boundary-Scan Register
SAMPLE/PRELOAD	81	1000 0001	Boundary-Scan Register
DCODE	AA	1010 1010	Device Identification Register
JNPARK	E7	1110 0111	Device Identification Register
PARKTLR	C5	1100 0101	Device Identification Register
PARKRTI	84	1000 0100	Device Identification Register
PARKPAUSE	C6	1100 0110	Device Identification Register
GOTOWAIT (Note 5)	C3	1100 0011	Device Identification Register
NODESEL	8E	1000 1110	Mode Register <sub>o</sub>
MODESEL1	82	1000 0010	Mode Register <sub>1</sub>
MODESEL2	83	1000 0011	Mode Register <sub>2</sub>
MODESEL3	85	1000 0101	Mode Register <sub>3</sub>
ICGRSEL	03	0000 0011	Multi-Cast Group Register
OFTRESET	88	1000 1000	Device Identification Register
FSRSEL	C9	1100 1001	Linear Feedback Shift Register
FSRON	0C	0000 1100	Device Identification Register
FSROFF	8D	1000 1101	Device Identification Register
NTRSEL	CE	1100 1110	32-Bit TCK Counter Register
NTRON	0F	0000 1111	Device Identification Register
NTROFF	90	1001 0000	Device Identification Register
EFAULT_BYPASS (Note 6)	07	0000 0111	Set Bypass_reg as default data register
RANSPARENT0	A0	1010 0000	Transparent Enable Registero
RANSPARENT1	A1	1010 0001	Transparent Enable Register1
RANSPARENT2	A2	1010 0010	Transparent Enable Register <sub>2</sub>
RANSPARENT3	A3	1010 0011	Transparent Enable Register <sub>3</sub>
RANSPARENT4	A4	1010 0100	Transparent Enable Register <sub>4</sub>
RANSPARENT5	A5	1010 0101	Transparent Enable Register5
RANSPARENT6	A6	1010 0110	Transparent Enable Register <sub>6</sub>
RANSPARENT7	A7	1010 0111	Transparent Enable Register <sub>7</sub>
OGPIO <sub>0</sub>	B0	1011 0000	Dedicated GPIO Register <sub>o</sub>
	B1	1011 0001	Dedicated GPIO Register <sub>1</sub>
GPIO <sub>2</sub>	B2	1011 0010	Dedicated GPIO Register <sub>2</sub>
	B3	1011 0011	Dedicated GPIO Register <sub>3</sub>

#### Level 2 Protocol (Continued)

TABLE 5. Level 2 Protocol and Op-Codes (Continued)				
Instructions	Hex Op-Code	Binary Op-Code	Data Register	
DGPIO <sub>4</sub>	B4	1011 0100	Dedicated GPIO Register <sub>4</sub>	
	B5	1011 0101	Dedicated GPIO Register <sub>5</sub>	
DGPIO <sub>6</sub>	B6	1011 0110	DedicateD GPIO Register <sub>6</sub>	
DGPIO <sub>7</sub>	B7	1011 0111	Dedicated GPIO Register <sub>7</sub>	
SGPIOo	B8	1011 1000	Shared GPIO Register <sub>0</sub>	
SGPIO <sub>1</sub>	B9	1011 1001	Shared GPIO Register <sub>1</sub>	
SGPIO <sub>2</sub>	BA	1011 1010	Shared GPIO Register <sub>2</sub>	
SGPIO <sub>3</sub>	BB	1011 1011	Shared GPIO Register <sub>3</sub>	
SGPIO <sub>4</sub>	BC	1011 1100	Shared GPIO Register <sub>4</sub>	
SGPIO₅	BD	1011 1101	Shared GPIO Register <sub>5</sub>	
SGPIO <sub>6</sub>	BE	1011 1110	Shared GPIO Register <sub>6</sub>	
SGPIO <sub>7</sub>	BF	1011 1111	Shared GPIO Register7	
Other Undefined	TBD	TBD	Device Identification Register	

Note 5: All other instructions act on selected STA111s only.

Note 6: Commands added to HDL version of STA111.

#### LEVEL 2 INSTRUCTON DESCRIPTIONS:

**BYPASS:** The *BYPASS* instruction selects the bypass register for insertion into the active scan chain when the 'STA111 is selected.

**EXTEST:** The *EXTEST* instruction selects the boundaryscan register for insertion into the active scan chain. The boundary-scan register consists of seven sample only shift cells connected to the S<sub>(0-6)</sub> and  $\overrightarrow{OE}$  inputs. On the 'STA111, the *EXTEST* instruction performs the same function as the *SAMPLE/PRELOAD* instruction, since there aren't any scannable outputs on the device.

**SAMPLE/PRELOAD:** The SAMPLE/PRELOAD instruction selects the boundary-scan register for insertion into the active scan chain. The boundary-scan register consists of seven sample only shift cells connected to the S<sub>(0-6)</sub> and  $\overline{OE}$  inputs.

**IDCODE:** The *IDCODE* instruction selects the device identification register for insertion into the active scan chain. When *IDCODE* is the current active instruction the device identification 0FC0F01F Hex is captured upon exiting the *Capture-DR* state.

**UNPARK:** This instruction unparks the Local Scan Port Network and inserts it into the active scan chain as configured by Mode Register<sub>0</sub> (and Mode Register<sub>1</sub> in the HDL) (see *Table 7*). Unparked LSPs are sequenced synchronously with the 'STA111's TAP controller. When a LSP has been parked in the *Test-Logic-Reset* or *Run-Test/Idle* state, it will not become unparked until the 'STA111's TAP Controller enters the *Run-Test/Idle* state following the *UNPARK* instruction. An LSP which has been parked in *Test-Logic-Reset* will be parked in *Run-Test/Idle* upon update of an *UNPARK* instruction. If an LSP has been parked in one of the stable pause states (*Pause-DR* or *Pause-IR*), it will not become unparked until the 'STA111's TAP Controller enters the respective pause state. (See *Figure 9*, *Figure 10*, *Figure 11*, and *Figure 12*).

**PARKTLR:** This instruction causes all unparked LSPs to be parked in the *Test-Logic-Reset* TAP controller state and removes the LSP network from the active scan chain. The LSP controllers keep the LSPs parked in the *Test-Logic*-

*Reset* state by forcing their respective  $TMS_n$  output with a constant logic 1 while the LSP controller is in the *Parked-TLR* state (see *Figure 4*).

**PARKRTI:** This instruction causes all unparked LSPs to be parked in the *Run-Test/Idle* state. The update of the *PARKRTI* instruction MUST immediately be followed by a TMS<sub>B</sub>=0 (to enter the *RTI* state) in order to assure stability. When a LSP<sub>n</sub> is active (unparked), its TMS<sub>n</sub> signals follow TMS<sub>B</sub> and the LSP<sub>n</sub> controller state transitions are synchronized with the TAP Controller state transitions of the 'STA111. When the instruction register is updated with the *PARKRTI* instruction, TMS<sub>n</sub> will be forced to a constant logic 0, causing the unparked local TAP Controllers to be parked in the *Run-Test/Idle* state. When an LSP<sub>n</sub> is parked, it is removed from the active scan chain.

**PARKPAUSE:** The *PARKPAUSE* instruction has dual functionality. It can be used to park unparked LSPs or to unpark parked LSPs. The instruction places all unparked LSPs in one of the TAP Controller pause states. A local port does not become parked until the 'STA111's TAP Controller is sequenced through *Exit1-DR/IR* into the *Update-DR/IR* state. When the 'STA111 TAP Controller is in the *Exit1-DR* or *Exit1-IR* state and TMSB is high, the LSP controller forces a constant logic 0 onto TMSL thereby parking the port in the *Pause-DR* or *Pause-IR* state respectively (see *Figure 4*). Another instruction can then be loaded to reconfigure the local ports or to deselect the 'STA111 (i.e., *MODESEL*, *GO-TOWAIT*, etc.).

If the *PARKPAUSE* instruction is given to a whose LSPs are parked in *Pause-IR* or *Pause-DR*, the parked LSPs will become unparked when the 'STA111's TAP controller is sequenced into the respective Pause state.

The *PARKPAUSE* instruction was implemented with this dual functionality to enable backplane testing (interconnect testing between boards) with simultaneous Updates and Captures.

Simultaneous Update and Capture of several boards can be performed by parking LSPs of the different boards in the *Pause-DR* TAP controller state, after shifting the data to be updated into the boundary registers of the components on each board. The broadcast address is used to select all

# Level 2 Protocol (Continued)

'STA111s connected to the backplane. The *PARKPAUSE* instruction is scanned into the selected 'STA111s and the 'STA111 TAP controllers are sequenced to the *Pause-DR* state where the LSPs of all 'STA111s become unparked. The local TAP controllers are then sequenced through the *Update-DR*, *Select-DR*, *Capture-DR*, *Exit1-DR*, and parked in the *Pause-DR* state, as the 'STA111 TAP controller is sequenced into the *Update-DR* state. When a LSP is parked, it is removed from the active scan chain.

**GOTOWAIT:** This instruction is used to return all 'STA111s to the *Wait-For-Address* state. All unparked LSPs will be parked in the *Test-Logic-Reset* TAP controller state (see *Figure 5*).

**MODESEL:** The MODESEL instruction inserts Mode Register<sub>0</sub> into the active scan chain. Mode Register<sub>0</sub> determines the LSPN configuration for a device with up to five (5) LSPs (only three in Silicon). Bit 7 of Mode Register<sub>0</sub> is a read-only counter status flag.

**MODESEL**<sub>n</sub>: The MODESEL<sub>n</sub> instruction inserts Mode Register<sub>n</sub> (n = 1 to 3) into the active scan chain. Mode Register<sub>1</sub> determines the LSPN configuration for LSP 5, 6 and 7 (if they exist), and Mode Register<sub>2</sub> determines the Shared GPIO configuration.

**MCGRSEL:** This instruction inserts the multi-cast group register (MCGR) into the active scan chain. The MCGR is used to group 'STA111s into multi-cast groups for parallel TAP sequencing (i.e., to simultaneously perform identical scan operations).

**SOFTRESET:** This instruction causes all 3 Port configuration controllers (see *Figure 4*) to enter the *Parked-TLR* state, which forces TMS<sub>n</sub> high; this parks each local port in the *Test-Logic-Reset* state within 5 TCK<sub>B</sub> cycles.

*LFSRSEL:* This instruction inserts the linear feedback shift register (LFSR) into the active scan chain, allowing a compacted signature to be shifted out of the LFSR during the *Shift-DR* state. (The signature is assumed to have been computed during earlier *LFSRON* shift operations.) This instruction disables the LFSR register's feedback circuitry, turning the LFSR into a standard 16-bit shift register. This

allows a signature to be shifted out of the register, or a seed value to be shifted into it.

*LFSRON:* Once this instruction is executed, the linear feedback shift register samples data from the active scan path (including all unparked  $\text{TDI}_n$ ) during the *Shift-DR* state. Data from the scan path is shifted into the linear feedback shift register and compacted. This allows a serial stream of data to be compressed into a 16-bit signature that can subsequently be shifted out using the *LFSRSEL* instruction. The linear feedback shift register is not placed in the scan chain during this mode. Instead, the register samples the active scan-chain data as it flows from the LSPN to TDO<sub>B</sub>.

*LFSROFF:* This instruction terminates linear feedback shift register sampling. The LFSR retains its current state after receiving this instruction.

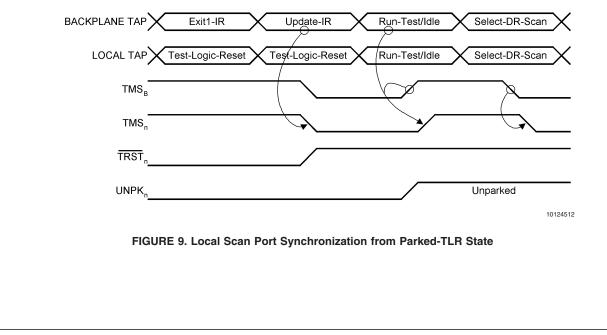
**CNTRSEL:** This instruction inserts the 32-bit TCK counter shift register into the active scan chain. This allows the user to program the number of n TCK cycles to send to the parked local ports once the *CNTRON* instruction is issued (e.g., for BIST operations). Note that to ensure completion of countdown, the 'STA111 should receive at least n TCK<sub>B</sub> pulses.

**CNTRON:** This instruction enables the TCK counter. The counter begins counting down on the first rising edge of TCK<sub>B</sub> following the *Update-IR* TAP controller state and is decremented on each rising edge of TCK<sub>B</sub> thereafter. When the TCK counter reaches terminal count, 00000000 Hex, TCK<sub>n</sub> of all parked LSP's is held low. This function overrides Mode Register<sub>o</sub> TCK control bit (bit-3).

If the *CNTRON* instruction is issued when the TCK counter is 00000000 (terminal count) the local TCKs of parked LSPs will be gated. The counter will begin counting on the rising edge of TCK<sub>B</sub> when the TCK counter is loaded with a non-zero value following a *CNTRSEL* instruction (see BIST Support in Special Features section for an example).

**CNTROFF:** This instruction disables the TCK counter, and  $TCK_n$  control is returned to Mode Register<sub>o</sub> (bit-3).

**DEFAULT\_BYPASS:** This instruction selects the Bypass register to be the default for SCANSTA111 commands that do not explicitly require a data register. The default after RESET is the Device ID register.



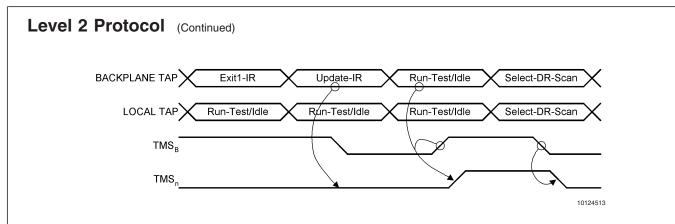


FIGURE 10. Local Scan Port Synchronization from Parked-RTI State

# **Register Descriptions**

SCANSTA111

**INSTRUCTION REGISTER:** The instruction shift register is an 8-bit register that is in series with the scan chain whenever the TAP Controller of the SCANSTA111 is in the *Shift-IR* state. Upon exiting the *Capture-IR* state, the value XXXXX01 is captured into the instruction register, where XXXXX represents the value on the S<sub>(0-6)</sub> inputs. When the 'STA111 controller is in the *Wait-For-Address* state, the instruction register is used for 'STA111 selection via address matching. In addressing individual 'STA111s, the chip's addressing logic performs a comparison between a staticallyconfigured (hard-wired) value on that 'STA111's slot inputs, and an address which is scanned into the chip's instruction register. Binary address codes 000000 through 111010 (00 through 3A Hex) are reserved for addressing individual 'STA111s. Address 3B Hex is for Broadcast mode.

During multi-cast (group) addressing, a scanned-in address is compared against the (previously scanned-in) contents of a 'STA111's Multi-Cast Group register. Binary address codes 111110 through 111111 (3A through 3F Hex) are reserved for multi-cast addressing, and should not be assigned as 'STA111 slot-input values.

**BOUNDARY-SCAN REGISTER:** The boundary-scan register is a sample only shift register containing cells from the  $S_{(0-6)}$  and  $\overline{OE}$  inputs. The register allows testing of circuitry external to the 'STA111. It permits the signals flowing between the system pins to be sampled and examined without interfering with the operation of the on-chip system logic.

The scan chain is arranged as follows:

 $\mathsf{TDI}_{\mathsf{B}} \rightarrow \overline{\mathsf{OE}} \rightarrow \mathsf{S}_{6} \rightarrow \mathsf{S}_{5} \rightarrow \mathsf{S}_{4} \rightarrow \mathsf{S}_{3} \rightarrow \mathsf{S}_{2} \rightarrow \mathsf{S}_{1} \rightarrow \mathsf{S}_{0} \rightarrow \mathsf{TDO}_{\mathsf{B}}$ 

**BYPASS REGISTER:** The bypass register is a 1-bit register that operates as specified in IEEE Std. 1149.1 once the 'STA111 has been selected. The register provides a minimum length serial path for the movement of test data between  $\text{TDI}_{B}$  and the LSPN. This path can be selected when no other test data register needs to be accessed during a board-level test operation. Use of the bypass register shortens the serial access-path to test data registers located in other components on a board-level test data path.

**MULTI-CAST GROUP REGISTER:** Multi-cast is a method of simultaneously communicating with more than one selected 'STA111. The multi-cast group register (MCGR) is a 2-bit

register used to determine which multi-cast group a particular 'STA111 is assigned to. Four addresses are reserved for multi-cast addressing. When a 'STA111 is in the *Wait-For-Address* state and receives a multi-cast address, and if that 'STA111's MCGR contains a matching value for that multicast address, the 'STA111 becomes selected and is ready to receive Level 2 Protocol (i.e., further instructions).

The MCGR is initialized to 00 upon entering the *Test-Logic-Reset* state.

TABLE 6. Multi-Cast Group Register Addressing

MCGR Bits 1,0	Hex Address	Binary Address
00	3C	00111100
01	3D	00111101
10	3E	00111110
11	3F	00111111

The following actions are used to perform multi-cast addressing:

- 1. Assign all target 'STA111s to a multi-cast group by writing each individual target 'STA111's MCGR with the same multi-cast group code (see *Table 6*). This configuration step must be done by individually addressing each target 'STA111, using that chip's assigned slot value.
- Scan out the multi-cast group address through the TDI<sub>B</sub> input of all 'STA111s. Note that this occurs in parallel, resulting in the selection of only those 'STA111s whose MCGR was previously programmed with the matching multi-cast group code.

**MODE REGISTER**<sub>0</sub>: Mode Register<sub>0</sub> is an 8-bit data register used primarily to configure the Local Scan Port Network. Mode Register<sub>0</sub> is initialized to 00000001 binary upon entering the *Test-Logic-Reset* state. Bits 0, 1, 2, and 4 are used for scan chain configuration as described in *Table 7*. When the *UNPARK* instruction is executed, the scan chain configuration is as shown in *Table 7* below. When all LSPs are parked, the scan chain configuration is TDI<sub>B</sub>  $\rightarrow$  'STA111-register  $\rightarrow$  TDO<sub>B</sub>. Bit 3 is used for TCK<sub>n</sub> configuration, see *Table 8*.

#### TABLE 7. Mode Register Control of LSPN

Mode Register(s)	Scan Chain Configuration (if unparked)
MR0: X000X000	$\text{TDI}_{B} \rightarrow \text{Register} \rightarrow \text{TDO}_{B}$
	1

Register Descriptions (Continued)			
	TABLE 7. Mode Register Control of LSPN (Continued)		
Mode Register(s)	Scan Chain Configuration (if unparked)		
MR0: X000X001	$\text{TDI}_{B} \rightarrow \text{Register} \rightarrow \text{LSP}_{0} \rightarrow \text{PAD} \rightarrow \text{TDO}_{B}$		
MR0: X000X010	$TDI_{B} \to Register \to LSP_{1} \to PAD \to TDO_{B}$		
MR0: X000X011	$TDI_{B} \to Register \to LSP_{0} \to PAD \to LSP_{1} \to PAD \to TDO_{B}$		
MR0: X000X100	$TDI_{B} \to Register \to LSP_2 \to PAD \to TDO_{B}$		
MR0: X000X101	$TDI_{B} \to Register \to LSP_0 \to PAD \to LSP_2 \to PAD \to TDO_{B}$		
MR0: X000X110	$TDI_{B} \to Register \to LSP_1 \to PAD \to LSP_2 \to PAD \to TDO_{B}$		
MR0: X000X111	$TDI_{B} \rightarrow Register \rightarrow LSP_{0} \rightarrow PAD \rightarrow LSP_{1} \rightarrow PAD \rightarrow LSP_{2} \rightarrow PAD \rightarrow TDO_{B}$		
MR0: X010X000	$\frac{TDI_{B} \to Register \to LSP_3 \to PAD \to TDO_{B}}{TDI_{B} \to Register \to LSP_3 \to PAD \to TDO_{B}}$		
MR0: X010X001	$\frac{TDI_{B} \to Register \to LSP_0 \to PAD \to LSP_3 \to PAD \to TDO_{B}}{TDI_{B} \to Register \to LSP_0 \to PAD \to LSP_3 \to PAD \to TDO_{B}}$		
MR0: X010X010	$\frac{TDI_{B} \to Register \to LSP_1 \to PAD \to LSP_3 \to PAD \to TDO_{B}}{TDI_{B} \to Register \to LSP_1 \to PAD \to LSP_3 \to PAD \to TDO_{B}}$		
MR0: X010X011	$TDI_{B} \rightarrow Register \rightarrow LSP_{0} \rightarrow PAD \rightarrow LSP_{1} \rightarrow PAD \rightarrow LSP_{5} \rightarrow PAD \rightarrow TDO_{B}$		
MR0: X010X100	$TDI_{B} \rightarrow Register \rightarrow LSP_{2} \rightarrow PAD \rightarrow LSP_{3} \rightarrow PAD \rightarrow TDO_{B}$		
 MR0: X110X111	$ \begin{array}{c} {\longrightarrow}\\ \text{TDI}_{\text{B}} \rightarrow \text{Register} \rightarrow \text{LSP}_{0} \rightarrow \text{PAD} \rightarrow \text{LSP}_{1} \rightarrow \text{PAD} \rightarrow \text{LSP}_{2} \rightarrow \text{PAD} \rightarrow \text{LSP}_{3} \rightarrow \text{PAD} \rightarrow \text{LSP}_{4} \rightarrow \text{PAD} \rightarrow \text{TDO}_{\text{B}} \end{array} $		
MR0: X000X000 MR1: XXXXX001 (Note 7)	$TDI_{B} \to Register \to LSP_5 \to PAD \to TDO_{B}$		
MR0: X000X001 MR1: XXXXX001 (Note 7)	$TDI_B \to Register \to LSP_0 \to PAD \to LSP_5 \to PAD \to TDO_B$		
MR0: X000X010 MR1: XXXXX001 (Note 7)	$TDI_B \to Register \to LSP_1 \to PAD \to LSP_5 \to PAD \to TDO_B$		
MR0: X110X111 MR1: XXXXX001 (Note 7)	$ \begin{array}{c} TDI_B \to Register \to LSP_0 \to PAD \to LSP_1 \to PAD \to LSP_2 \to PAD \to LSP_3 \to PAD \to LSP_4 \to PAD \\ \to LSP_5 \to PAD \to TDO_B \end{array} $		
MR0: X000X000 MR1: XXXXX010 (Note 7)	$TDI_{B} \to Register \to LSP_{6} \to PAD \to TDO_{B}$		
MR0: X110X111 MR1: XXXXX111 (Note 7)	$ \begin{array}{l} TDI_B \to Register \to LSP_0 \to PAD \to LSP_1 \to PAD \to LSP_2 \to PAD \to LSP_3 \to PAD \to LSP_4 \to PAD \to LSP_5 \to PAD \to LSP_6 \to PAD \to LSP_7 \to PAD \to TDO_B \end{array} $		
MR0: XXX1XXXX MR1: XXXXXXXX (Note 7)	$\text{TDI}_{B} \rightarrow \text{Register} \rightarrow \text{TDO}_{B}$ (Loopback)		

**Note 7:** Mode Register<sub>1</sub> is only available in the HDL version (up to eight LSPs). The Silicon version has three LSPs and uses Mode Register<sub>0</sub> only. **Note 8:** In a device with 8 LSPs there are 2<sup>8</sup> possible LSPN configurations: No LSPs, each individual LSP, combinations of 2 to 7 LSPs, and all 8 LSPs.

**TABLE 8. Test Clock Configuration** 

Bit 3	LSP n	TCK n
1	Parked	Stopped
0	Parked	Free-running
1	Unparked	Free-running
0	Unparked	Free-running
Х	Parked-TLR	Stopped after 512 clock pulses

Bit 3 is normally set to logic 0 so that  $TCK_n$  is free-running when the local scan ports are parked in the *Parked-RTI*,

*Parked-Pause-DR* or *Parked-Pause-IR* state. When the local ports are parked, bit 3 can be programmed with logic 1, forcing all of the LSP TCK<sub>n</sub>'s to stop. This feature can be used in power sensitive applications to reduce the power consumed by the test circuitry in parts of the system that are not under test. When in the *Parked-TLR* state, TCK<sub>n</sub> is gated (stopped) after 512 clock pulses have been received on TCK<sub>B</sub> independent of the bit 3 value.

Bit 7 is a status bit for the TCK counter. Bit 7 is only set (logic 1) when the TCK counter is on and has reached terminal

SCANSTA111

## **Register Descriptions** (Continued)

count (zero). It is cleared (logic 0) when the counter is loaded following a *CNTRSEL* instruction. The power-on value for bit 7 is 0.

Bits 5 and 6 are optional in the HDL to support five LSPs with a single Mode  $\text{Register}_0$ . A second Mode  $\text{Register}_1$  may be added to allow support of up to eight LSPs.

BIT	7	6	5	4	3	2	1	0
Description	TCK Counter Status	$LSP_4$	$LSP_3$	$TDI_B$ to $TDO_B$ Loopback	TCK Free Running Disable	$LSP_2$	$LSP_1$	LSP <sub>0</sub>
Used in Silicon	Y	Ν	Ν	Υ	Υ	Υ	Y	Y
Default Value	0	0	0	0	0	0	0	1

TABLE 9. Mode Register

TABLE 10. Mode Register1									
BIT	7	6	5	4	3	2	1	0	
Description	Reserved	Reserved	Reserved	Reserved	Reserved	LSP <sub>7</sub>	LSP <sub>6</sub>	LSP₅	
Used in Silicon	N	N	N	N	N	N	N	N	
Default Value	0	0	0	0	0	0	0	0	

#### TABLE 11. Mode Register<sub>2</sub>

BIT	7	6	5	4	3	2	1	0
Description	LSP7/GPIO7	LSP <sub>6</sub> /GPIO <sub>6</sub>	$LSP_5/GPIO_5$	LSP <sub>4</sub> /GPIO <sub>4</sub>	LSP <sub>3</sub> /GPIO <sub>3</sub>	$LSP_2/GPIO_2$	$LSP_1/GPIO_1$	LSP <sub>0</sub> /GPIO <sub>0</sub>
Used in Silicon	Ν	Ν	Ν	Ν	Ν	Y	Υ	Y
Default Value	0	0	0	0	0	0	0	0

**DEVICE IDENTIFICATION REGISTER:** The device identification register (IDREG) is a 32-bit register compliant with IEEE Std. 1149.1. When the *IDCODE* instruction is active, the identification register is loaded with the Hex value upon leaving the *Capture-DR* state (on the rising edge of the TCK<sub>B</sub>). Refer to the currently available BSDL file on our website for the most accurate Device ID.

LINEAR FEEDBACK SHIFT REGISTER: The 'STA111 contains a signature compactor which supports test result evaluation in a multi-chain environment. The signature compactor consists of a 16-bit linear-feedback shift register (LFSR) which can monitor local-port scan data as it is shifted upstream from the 'STA111's local-port network. Once the LFSR is enabled, the LFSR's state changes in a reproducible way as each local-port data bit is shifted in from the local-port network. When all local-port data has been scanned in, the LFSR contains a 16-bit signature value which can be compared against a signature computed for the expected results vector.  $\mathsf{F}(\mathsf{x}) = \mathsf{X}^{16} + \mathsf{X}^{12} + \mathsf{X}^3 + \mathsf{X} + \mathsf{1}$ 

This signature compactor is used to compress serial data shifted in from the local scan chain, into a 16-bit signature. This signature can then be shifted out for comparison with an expected value. This allows users to test long scan chains in parallel, via Broadcast or Multi-Cast addressing modes, and check only the 16-bit signatures from each module. The LFSR is initialized with a value of 0000 Hex upon reset.

**32-BIT TCK COUNTER REGISTER:** The 32-bit TCK counter register enables BIST testing that requires n TCK cycles, to be run on a parked LSP while another 'STA111 port is being tested. The *CNTRSEL* instruction can be used to load a count-down value into the counter register via the active scan chain. When the counter is enabled (via the *CNTRON* instruction), and the LSP is parked, the local TCKs will stop and be held low when terminal count is reached.

The TCK counter is initialized with a value of 00000000 Hex upon reset.

The LFSR uses the following feedback polynomial:

BIT	7	6	5	4	3	2	1	0
Description	Input	Input	Input	Input	Output	Output	Output	Output

TABLE 10. Offared of to Hegistern										
BIT	7	6	5	4	3	2	1	0		
Description	Reserved	Reserved	Reserved	Reserved	Reserved	Input (TDI)	Output (TDO)	Output (TMS)		
Used in Silicon	N	N	N	N	N	Y	Y	Y		
Default Value	0	0	0	0	0	0	0	0		

#### TABLE 13. Shared GPIO Register,

# **Special Features**

#### TRANSPARENT MODE

While this mode is activated, the selected LSP n ports will follow the backplane ports.  $\overline{TRST}_n$  is a buffered version of  $\overline{TRST}_B$ , TCK<sub>n</sub> is a buffered version of TCK<sub>B</sub>, TMS<sub>n</sub> is a buffered version of TDI<sub>B</sub> and TDO<sub>B</sub> is a buffered version of TDI<sub>n</sub>. TRIST<sub>B</sub> and TRIST<sub>n</sub> are asserted when the state machine is in either the *Shift-DR* or *Shift-IR* states. The unselected LSPs are placed in the *PARKTLR* state, and their clocks are gated after 512 TCK<sub>B</sub> clock cycles.

Transparent Mode is controlled by 8 new instructions, *TRANSPARENTO* through *TRANSPARENT7*. Transparent Mode overrides any other active mode. When one of the transparent mode instruction is shifted into the instruction register and the tap controller goes through the *UPDATE-IR* state,  $\overline{TRST}_n$  will go high, and  $TMS_n$  will go low. This will force the targets connected to the LSP<sub>n</sub> ports to go into the *RTI* state. Then as the STA111 state machine goes into the *RTI* state, all of the LSP<sub>n</sub> signals will follow the back-plane signals. This is identical to the method that is typically used to unpark an LSP. The STA111 will remain in this mode until a TRST<sub>B</sub> is asserted or a power cycle forces a reset. Once in the Transparent Mode, the STA111 will not be able to be reset by a 5 TMS high reset.

The sequence of operations to use Transparent Mode on an LSP are as follows (example uses  $\text{LSP}_{0}$  ):

- 1. IR-Scan the STA111 address into the instruction register (address a STA111).
- 2. IR-Scan the *TRANSPARENTO* instruction to enable Transparent Mode on LSP<sub>0</sub>. Transparent Mode is enabled when the TAP enters the *RTI* state at the end of this shift operation ( $\overline{TRST}_0$ ,  $\underline{TDO}_0$ ,  $\underline{TMS}_0$  and  $\underline{TCK}_0$  become buffered versions of  $\overline{TRST}_B$ ,  $\underline{TDI}_B$ ,  $\underline{TMS}_B$  and  $\underline{TCK}_B$  and  $\underline{TDO}_B$  becomes a buffered version of  $\underline{TDI}_0$ ).

NOTE: Transparent Mode will persist until the STA111 is reset using  $\overline{TRST}_{\rm B}$ . The *GOTOWAIT* and *SOFTRESET* instructions will not work in this mode.

#### **BIST SUPPORT**

The sequence of instructions to run BIST testing on a parked SCANSTA111 port is as follows:

- 1. Pre-load the Boundary register of the device under test if needed.
- 2. Issue the *CNTRSEL* instruction and initialize (load) the TCK counter to 00000000 Hex. Note that the TCK counter is initialized to 00000000 Hex upon *Test-Logic-Reset*, so this step may not be necessary.
- 3. Issue the *CNTRON* instruction to the 'STA111, to enable the TCK counter.
- 4. Shift the *PARKRTI* instruction into the 'STA111 instruction register and *BIST* instruction into the instruction register of the device under test. With the counter on (at terminal count) and the LSP parked, the local TCK is gated.
- 5. Issue the *CNTRSEL* instruction to the 'STA111.

- 6. Load the TCK counter (Shift the 32-bit value representing the number of TCK<sub>n</sub> cycles needed to execute the BIST operation into the TCK counter register). The Self test will begin on the rising edge of TCK<sub>B</sub> following the *Update-DR* TAP controller state.
- Bit 7 of Mode Register<sub>o</sub> can be scanned to check the status of the TCK counter, (*MODESEL* instruction followed by a *Shift-DR*). Bit 7 logic 0 means the counter has not reached terminal count, logic 1 means that the counter has reached terminal count and the BIST operation has completed.
- 8. Execute the *CNTROFF* instruction.
- 9. Unpark the LSP and scan out the result of the BIST operation

#### RESET

Reset operations can be performed at three levels. The highest level resets all 'STA111 registers and all of the local scan chains of selected and unselected 'STA111s. This Level 1 reset is performed whenever the 'STA111 TAP Controller enters the *Test-Logic-Reset* state. *Test-Logic-Reset* can be entered synchronously by forcing TMS<sub>B</sub> high for at least five (5) TCK<sub>B</sub> pulses, or asynchronously by asserting the TRST<sub>B</sub> pin. A Level 1 reset forces all 'STA111s into the *Wait-For-Address* state, parks all local scan chains in the *Test-Logic-Reset* state, and initializes all 'STA111 registers.

The *SOFTRESET* instruction is provided to perform a Level 2 reset of all LSP's of selected 'STA111s. *SOFTRESET* forces all TMS<sub>n</sub> signals high, placing the corresponding local TAP Controllers in the *Test-Logic-Reset* state within five (5) TCK<sub>B</sub> cycles.

The third level of reset is the resetting of individual local ports. An individual LSP can be reset by parking the port in the *Test-Logic-Reset* state via the *PARKTLR* instruction. To reset an individual LSP that is parked in one of the other parked states, the LSP must first be unparked via the *UN-PARK* instruction.

#### PORT SYNCHRONIZATION

When a LSP is not being accessed, it is placed in one of the four TAP Controller states: *Test-Logic-Reset*, *Run-Test/ldle*, *Pause-DR*, or *Pause-IR*. The 'STA111 is able to park a local chain by controlling the local Test Mode Select outputs (TMS<sub>(0-2)</sub>) (see *Figure 4*). TMS<sub>n</sub> is forced high for parking in the *Test-Logic-Reset* state, and forced low for parking in *Run-Test/ldle*, *Pause-IR*, or *Pause-DR* states. Local chain access is achieved by issuing the *UNPARK* instruction. The LSPs do not become unparked until the 'STA111 TAP Controller is sequenced through a specified synchronization state. Synchronization occurs in the *Run-Test/ldle* state for LSPs parked in *Test-Logic-Reset* or *Run-Test/ldle*; and in the *Pause-DR* or *Pause-IR* state for ports parked in *Pause-DR* or *Pause-IR*, respectively.

Figure 11 and Figure 12 show the waveforms for synchronization of a local chain that was parked in the *Test-Logic-Reset* state. Once the *UNPARK* instruction is received in the instruction register, the LSPC forces  $TMS_n$  low on the falling edge of  $TCK_B$ .

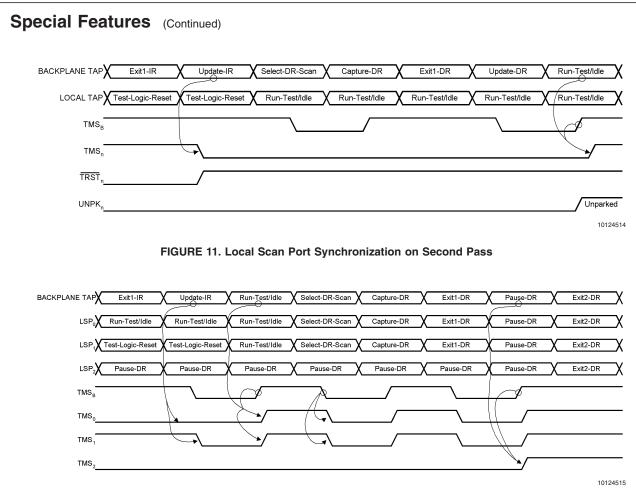


FIGURE 12. Synchronization of the Three Local Scan Ports

This moves the local chain TAP Controllers to the synchronization state (*Run-Test/ldle*), where they stay until synchronization occurs. If the next state of the 'STA111 TAP Controller is *Run-Test/ldle*, TMS<sub>n</sub> is connected to TMS<sub>B</sub> and the local TAP Controllers are synchronized to the 'STA111 TAP Controller as shown in *Figure 12*. If the next state after *Update-IR* were *Select-DR*, TMS<sub>n</sub> would remain low and synchronization would not occur until the 'STA111 TAP Controller entered the *Run-Test/ldle* state, as shown in *Figure 11*.

Each local port has its own Local Scan Port Controller. This is necessary because the LSPN can be configured in any one of eight (8) possible combinations. Either one, some, or all of the local ports can be accessed simultaneously. Configuring the LSPN is accomplished with Mode Register<sub>o</sub>, in conjunction with the *UNPARK* instruction.

The LSPN can be unparked in one of seven different configurations (Si device), as specified by bits 0-2 of Mode Register<sub>0</sub>. Using multiple ports presents not only the task of synchronizing the 'STA111 TAP Controller with the TAP Controllers of an individual local port, but also of synchronizing the individual local ports to one another.

When multiple local ports are selected for access, it is possible that two ports are parked in different states. This could occur when previous operations accessed the two ports separately and parked them in the two different states. The LSP Controllers handle this situation gracefully. *Figure 12* shows the *UNPARK* instruction being used to access LSP<sub>o</sub>, LSP<sub>1</sub>, and LSP<sub>2</sub> in series (Mode Register<sub>0</sub> = XXX0X111 binary). LSP<sub>0</sub> and LSP<sub>1</sub> become active as the 'STA111 controller is sequenced through the *Run-Test/Idle* state. LSP<sub>2</sub> remains parked in the *Pause-DR* state until the 'STA111 TAP Controller is sequenced through the *Pause-DR* state. At that point, all three local ports are synchronized for access via the active scan chain.

#### PARAMETERIZED DESIGN (HDL)

In order to support a large number of applications, the STA111 HDL is to parameterized as described:

- Number of Local Scan Ports (LSPs): The STA111 HDL is able to simulate/synthesize a device that contains from 1 to 8 LSPs. LSP<sub>0</sub> through LSP<sub>4</sub> are controlled via Mode Register<sub>0</sub> and LSP<sub>5</sub> through LSP<sub>7</sub> are controlled via Mode Register<sub>1</sub>.
- Number of Address Pins: The STA111 has a selectable number of address bits (S<sub>o</sub> - S<sub>n</sub>, where n can range from 5 to 7). Addresses 3A through 3F hex are reserved for address interrogation, broadcast and multi-cast addressing.
- **Pass-Through Pins:** Each of the LSPs (0-n) may selectivly have or not have Pass-through pins. Pass-through pins are described in more detail below.

# Special Features (Continued)

Number/Type of GPIO bits: The STA111 has both dedicated and shared GPIO (General Purpose I/O). Each dedicated group of GPIO bits supports from 0 to 4 dedicated inputs and 0 to 4 dedicated outputs. There are provisions for specifying the default (power-up) value. TMS<sub>(0-n)</sub>, TDO<sub>(0-n)</sub> and TDI<sub>(0-n)</sub> are also dual purpose pins functioning as LSP or GPIO. TMS<sub>n</sub> and TDO<sub>n</sub> are outputs, TDI<sub>n</sub> is an input in the GPIO mode.

Throught this datasheet, notations exist to clarify the differences between features available on the Silicon version and the HDL version.

#### KNOWN POWER-UP STATE

The STA111 has a known power-up condition. This is the same state that the device is in after a  $\overline{\text{TRST}}$  reset. This happens at power-up without the presence of a TCK<sub>B</sub>.

Reset can also occur via a 5 TMS high reset or a *SOFTRE-SET* command.

# POWER-OFF HIGH IMPEDANCE INPUTS AND OUTPUTS

The STA111 backplane test port features power-off high impedance inputs and outputs.

The TDI<sub>B</sub>, TMS<sub>B</sub>, and TRST<sub>B</sub> inputs have a 25K $\Omega$  pull-up resistor and no ESD clamp diode (ESD is controlled with an alternate method). When the device is power-off (V<sub>DD</sub> floating), these inputs appear to be a capacitive load to ground. When V<sub>DD</sub> = 0V (i.e.; not floating but tied to V<sub>SS</sub>) these inputs appear to be capacitive with the pull-up to ground.

The TCK<sub>B</sub> input has no pull-up resistor and no ESD clamp diode (ESD is controlled with an alternate method). When the device is power-off ( $V_{DD}$  floating), the input appears to be a capacitive load to ground. When  $V_{DD} = 0V$  (i.e.; not floating but tied to  $V_{SS}$ ) the input appears to be a capacitive load to ground.

When the device is power-off (V\_{DD} = 0V or floating), the TDO<sub>B</sub> output appears to be a capacitive load.

Refer to the device IBIS model on our website for more details about the I/O characteristics at http:// www.national.com/appinfo/scan/ibis.html.

#### TRST

 $\overline{\text{TRST}}_{\text{B}}$ : Assertion of  $\overline{\text{TRST}}_{\text{B}}$  will return the device back to its known power-up state.

**TRST**<sub>n</sub>: TRST<sub>n</sub> is an output on the LSP side of the STA111. While the LSP state-machine (level 2 protocol) is in the *Parked-TLR* state the TRST<sub>n</sub> pin will be driven low. In all other states the TRST<sub>n</sub> pin will be driven high.

#### PHYSICAL LAYER CHANGES

TRIST for TDO<sub>B</sub> and TDO<sub>n</sub> are signals for enabling an external buffer circuit between the 'STA111 and the backplane/LSP. This would allow, for example, a CMOS-to-LVDS converter to drive an LVDS JTAG backplane test bus. These signals are always driving. A seperate TRIST is provided for each LSP to report a TRI-STATE on TDO when the LSP is not in a shift state.

#### SVF DRIVEN, SELF-CHECKING TEST BENCH

The STA111 consists of 3 types of pins, dot1 backplane pins, dot1 LSP pins and support pins. The command interpreter of the test bench is able to translate a limited set of SVF

commands to the dot1 backplane pins. The SVF shift commands contain both the stimulus (TDI\_B) and expected response (TDO\_B).

The interpreter is able to parse the following commands: *ENDDR*, *ENDIR*, *RUNTEST*, *SDR*, *SIR*, *STATE*, *TRST*.

#### PASS-THROUGH PINS

Each LSP may selectively have two pass-through pins. The pair of pass-through pins consist of an input  $(A_n)$  and an output  $(Y_n)$ . The LSP pass-through output  $(Y_n)$  drives the level being received by the backplane pass-through input  $(A_B)$ . Conversly, the level on the LSP pass-through input  $(A_n)$  drives the backplane pass-through output  $(Y_B)$ .

The Pass-through pins are available only when a single LSP is selected. For each LSP these pins will be enabled when the level 2 protocol state-machine is not in the *Parked-TLR* state. When not enabled they are TRI-STATED.

#### LSP GATING

While the LSP state-machine (level 2 protocol) is in the *Parked-TLR* state, the four LSP signals shall be controlled as shown in *Table 14* below. Upon entry into the *Parked-TLR* state (*power-up*, *reset*, *PARKTLR* or *GOTOWAIT*) a counter in the LSP state-machine allows 512 TCK<sub>B</sub> clock pulses to occur on TCK<sub>n</sub> before gating. Once gated, TCK<sub>n</sub> will drive a logic 0.

Letting 512 TCK<sub>B</sub> pulses pass through to TCK<sub>n</sub> allows a five high TMS reset to occur on over 100 levels of hierarchy before the STA111 gates TCK<sub>n</sub> (for power saving in a free-running clock system).

LSP	Drive State
Connection	
TDO <sub>n</sub>	Pull-up resistor to provide a weak HIGH
TMS <sub>n</sub>	Pull-up resistor to provide a weak HIGH
TDIn	Pull-up resistor to provide a weak HIGH
TCK <sub>n</sub>	TCK <sub>B</sub> for 512 pulses, then gated LOW

TABLE 14. Gated LSP Drive States

The STA111 does not require that any clock pulses are received on TCK\_B while in the <code>Parked-TLR</code> state.

Setting Bit 3 of Mode Register<sub>o</sub> to 1 gates TCK<sub>n</sub> when in the *Parked-RTI*, *Parked-Pause-DR* and *Parked-Pause-IR* states. Default is free-running (bit 3 = 0). The value stored in bit 3 of Mode Register<sub>o</sub> does not effect the requirement of 512 clock pulses before gating TCK<sub>n</sub> in the *Parked-TLR* state. (See section on Mode Register<sub>o</sub>).

#### **IEEE 1149.4 SUPPORT**

The STA111 provides support for a switched analog bus. Each LSP has an unparked-TLR notification pin (LSP\_ACTIVE<sub>(0-2)</sub>) which is low (0) when the LSP is in *Parked-TLR* and high (1) otherwise. This signal can be used to enable/disable analog switches external to the STA111.

#### **GPIO CONNECTIONS**

General Purpose I/O (GPIO) pins are registered inputs and outputs that are parameterized in the HDL. The two types of GPIOs than can be used in the STA111 are described in the next two sections.

**DEDICATED:** Each LSP supports up to four (4) dedicated inputs and up to four (4) dedicated outputs. These are seperate, dedicated GPIO signals controlled by dedicated GPIO

#### Special Features (Continued)

registers (one register per LSP). The GPIO outouts are updated during the *UPDATE-DR* state and the GPIO input values are written to the corresponding GPIO register during the *CAPTURE-DR* state.

**LSP SHARED:** In the shared mode of opeartion, the dot1 LSP pins  $\text{TDI}_n$ ,  $\text{TDO}_n$  and  $\text{TMS}_n$  pins become GPIO pins.  $\text{TMS}_n$  and  $\text{TDO}_n$  are outputs,  $\text{TDI}_n$  is an input in the GPIO mode.

The sequence of operations to use shared GPIOs on an LSP are as follows (example uses LSP<sub>0</sub>):

- 1. IR-Scan the STA111 address into the instruction register (address a STA111).
- IR-Scan the *MODESEL*<sub>3</sub> instruction into the instruction register to select Mode Register<sub>3</sub> (Shared GPIO configuration register) as the data register.
- 3. DR-Scan 00000001 into Mode Register<sub>3</sub> to enable GPIOs on LSP<sub>0</sub>. The GPIOs will be enabled when the TAP enters the *RTI* state at the end of this shift operation (TDO<sub>0</sub> and TMS<sub>0</sub> will be forced to logic 0 as defined by the default value in the Shared GPIO Register<sub>0</sub>).
- IR-Scan the SGPIO<sub>0</sub> instruction into the instruction register to select the Shared GPIO Register<sub>0</sub> as the data register.
- 5. DR-Scan 00000011 into the Shared GPIO Register<sub>o</sub> to set TDO<sub>o</sub> and TMS<sub>o</sub> to a logic 1 (when TAP enters *Update-DR*). During this operation, when the TAP enters *Capture-DR*, the present value on the TDI<sub>o</sub> pin and the values of TDO<sub>o</sub> and TMS<sub>o</sub> (as set by Shared GPIO Register<sub>o</sub>) will be captured into bits 2, 1 and 0 of the shift register and will be scanned out 00000X00 (X = value present on TDI<sub>o</sub> when TAP enters *Capture-DR*).
- 6. Step 5 can be repeated to generate waveforms on  $TDO_0$ and  $TMS_0$ . If step 5 was repeated with 00000000 as data,  $TDO_0$  and  $TMS_0$  would be set to a logic 0 (when TAP state = *Update-DR*) and 00000X11 would be scanned out (X = value present on  $TDI_0$  when TAP enters *Capture-DR*).
- 7. IR-Scan the *GOTOWAIT* or *SOFTRESET* instruction, or generate a  $\overline{\text{TRST}}_{\text{B}}$  reset to disable the GPIOs.

#### ADDRESS INTERROGATION

The STA111 has four states that it can goto from the *Wait-For-Address* state: *Unselected, Singularly-selected, Multi/* Broadcast-selected, and Address-interrogation (see Figure 13).

After a reset (or GOTOWAIT command) has been issued, the STA111 TAP is sequenced to the Capture-IR state where XXXXXX01 is loaded into the shift register. Upon entering the Shift-IR state, the instruction register is filled with the address interrogation value (3A hex) which is loaded into the address register as the TAP is sequenced into the Update-IR state. On the next loop through Capture-IR the shift register is loaded with the ones-complement of the slot address. In the Shift-IR state the address interrogation value is loaded into the instruction register. The value presented on TDO<sub>B</sub> will be a wired-and address of all of the STA111s on the bus. As this value is being shifted out, each STA111 will monitor its TDO<sub>B</sub> to see if it is receiving the same value it is driving. If the device shifts all bits of its ones-complement address and never gets a compare error it will tri-state TDO<sub>B</sub> and go to the Wait-For-Reset state. Alternately, if the device sees a compare error while it is shifting its ones-complement address it will stop shifting its address and tri-state TDO<sub>B</sub> until

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the next shift operation; during the next *Shift-IR* operation it will again try to present its address (if the previous instruction was 3A hex) while monitoring  $TDO_B$ .

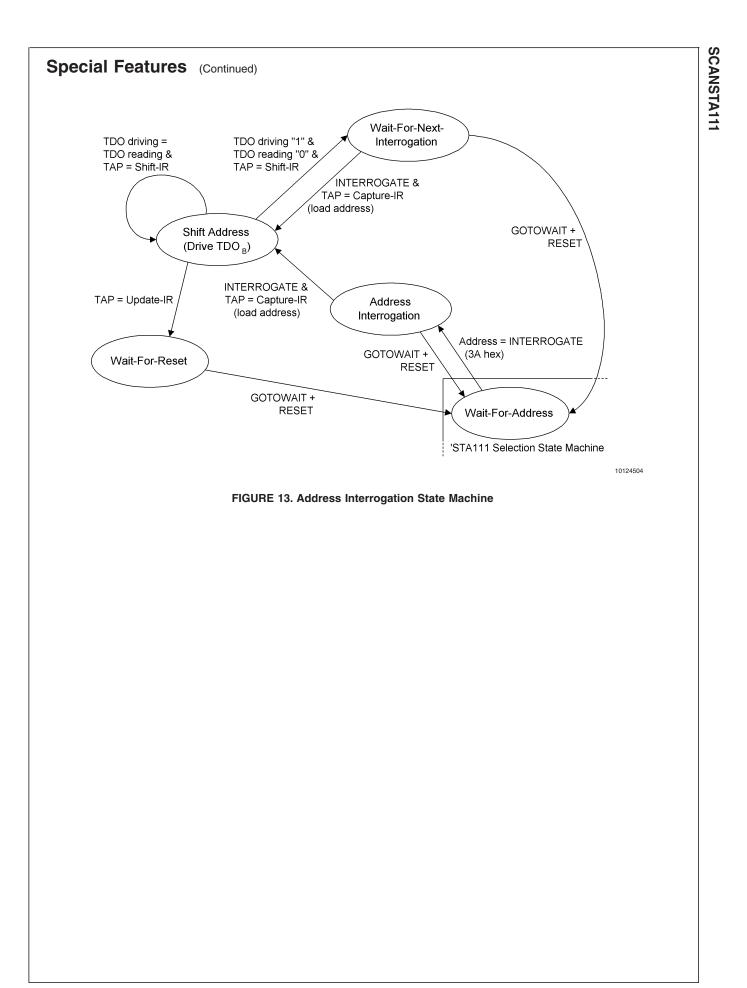
Shifting 3A hex into the instruction registers of the STA111s will continue until all STA111s have presented their address. At this time all devices will be waiting to be reset, and if a 3A is shifted into the STA111 instruction registers the address read by the tester will be all weak 1s due to all TDO<sub>B</sub>'s being tri-stated. Reading all ones will signal the tester that address interrogation is complete. Since all ones signifies the end of *Address-Interrogation*, no device can have an address of all zeros (ones-complement).

If at any time, during the address interrogation mode, any other instruction besides 3A hex is shifted into the instruction register, then the STA111 will exit the interrogation mode. Also, the STA111's state machine will go to the *Wait-For-Address* state.

This address interrogation scheme presumes that  $TDO_B$  is capable of driving a weak 1 and that an STA111 driving a 0 will overdrive an STA111 driving a weak 1.

The following is an example of the *Address-Interrogation* function. Assume there are three STA111s (U1, U2 and U3) on a dot1 backplane with slot addresses 010100, 100000 and 000001 respectively (assuming 6 address pins).

- 1. The STA111s are reset and the interrogation address/ op-code (3A hex) is shifted into the instruction registers.
- 2. At the end of the instruction shift (*Update-IR*) the STA111 address registers are loaded with 3A hex.
- 3. The TAPs are sequenced to *Capture-IR* and the shift registers latch the ones-complement slot addresses (U1=101011, U2=011111 and U3=111110).
- 4. The TAPs are sequenced to *Shift-IR* and the LSB of the interrogation address is presented on the  $\text{TDI}_{B}$ 's. Concurrently, the LSBs of the ones-complement slot addresses are presented on the respective  $\text{TDO}_{B}$ 's.
- 5. The weak 1 being driven on U1 and U2 is overdriven by the 0 from U3. U1 and U2 enter the *Wait-For-Next-Interrogation* state.
- The shift operation continues and U3 finishes shifting its ones-complement address (111110) out on TDO<sub>B</sub>. U3 enters the *Wait-For-Reset* state when the TAP enters *Update-IR*.
- The TAPs are again sequenced to *Capture-IR* and U1 and U2 shift registers latch the ones-complement addresses (U1=101011, U2=011111).
- 8. The TAPs are sequenced to *Shift-IR* and the LSB of the interrogation address is presented on the  $TDI_B$ 's. Concurrently, the LSBs of the ones-complement addresses are presented on the respective  $TDO_B$ 's.
- 9. Since both U1 and U2 are driving a weak 1 the shift continues.
- 10. Again U1 and U2 drive weak 1 and the shift continues.
- 11. U2s weak 1 is overdriven by U1s 0 and U2 enters the *Wait-For-Next-Interrogation* state.
- 12. The shift operation continues and U1 finishes shifting its ones-complement address (101011) out on  $TDO_B$ . U1 enters the *Wait-For-Reset* state.
- 13. The instruction shift operation is repeated and U2 shifts its ones-complement address (011111) out on  $TDO_B$ . U2 enters the *Wait-For-Reset* state.
- 14. The instruction shift operation is repeated, however, all devices have been interrogated and are waiting for a reset. The master device will receive all ones. This implies that there can not be an STA111 with address 0!



# Absolute Maximum Ratings (Note 9)

Supply Voltage (V <sub>CC</sub> )	-0.3V to +4.0V
DC Input Diode Current (I <sub>IK</sub> )	
$V_1 = -0.5V$	–20 mA
DC Input Voltage (V <sub>I</sub> )	-0.5V to +3.9V
DC Output Diode Current (I <sub>OK</sub> )	
$V_{O} = -0.5V$	–20 mA
DC Output Voltage (V <sub>O</sub> )	-0.3V to +3.9V
DC Output Source/Sink Current (I <sub>O</sub> )	±50 mA
DC $V_{CC}$ or Ground Current	±50 mA
per Output Pin	
DC Latchup Source or Sink Current	±300 mA
Junction Temperature (Plastic)	15000
ounouon remperature (riaouo)	+150°C
Storage Temperature	+150 C -65°C to +150°C
-	
Storage Temperature	
Storage Temperature Lead Temperature (Solder, 4sec)	-65°C to +150°C
Storage Temperature Lead Temperature (Solder, 4sec) 49L BGA	-65°C to +150°C 235°C
Storage Temperature Lead Temperature (Solder, 4sec) 49L BGA 48L TSSOP	-65°C to +150°C 235°C
Storage Temperature Lead Temperature (Solder, 4sec) 49L BGA 48L TSSOP Max Pkg Power Capacity @ 25°C	-65°C to +150°C 235°C 260°C

49L BGA	85°C/W
48L TSSOP	85°C/W
Package Derating	11.8 mW/°C above
	25°C
ESD Last Passing Voltage (Min)	
I/O	2000V
Inputs	1000V

# Recommended Operating Conditions

Supply Voltage (V <sub>CC</sub> )	
'STA111	3.0V to 3.6V
Input Voltage (V <sub>I</sub> )	0V to $V_{\rm CC}$
Output Voltage (V <sub>O</sub> )	0V to $V_{\rm CC}$
Operating Temperature (T <sub>A</sub> )	
Industrial	-40°C to +85°C

**Note 9:** Absolute maximum ratings are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature, and output/input loading variables. National does not recommend operation of SCAN STA products outside of recommended operation conditions.

# **DC Electrical Characteristics**

Over recommended operating supply voltage and temperature ranges unless otherwise specified

Symbol	Parameter	Conditions	Min	Max	Units
V <sub>IH</sub>	Minimum High Input Voltage	V <sub>OUT</sub> = 0.1V or V <sub>CC</sub> -0.1V	2.1		V
V <sub>IL</sub>	Maximum Low Input Voltage	$V_{OUT} = 0.1V \text{ or}$ $V_{CC} - 0.1V$		0.8	V
V <sub>OH</sub>	Minimum High Output Voltage (TDO <sub>B</sub> , TCK <sub>(0-2)</sub> , TMS <sub>(0-2)</sub> , TDO <sub>(0-2)</sub> , Y <sub>(0-1)</sub> )	$I_{OUT} = -100 \ \mu A$ $V_{IN} (TDI_B, TMS_B, TCK_B)$ $= V_{IH}$	V <sub>CC</sub> - 0.2v		V
V <sub>OH</sub>	$\label{eq:constraint} \begin{array}{l} \mbox{Minimum High Output Voltage} \\ (TDO_{B}, \mbox{TCK}_{(0-2)}, \mbox{TMS}_{(0-2)}, \mbox{TDO}_{(0-2)}, \mbox{Y}_{(0-1)}, \mbox{Y}_{B}, \\ \hline \hline \mbox{TRST}_{(0-2)}) \end{array}$	$I_{OUT} = -24$ mA, $V_{IN}$ on S <sub>(0-6)</sub> and TDI <sub>(0-2)</sub> = V <sub>IH</sub> , V <sub>IL</sub> All Outputs Loaded	2.2		V
V <sub>OH</sub>	Minimum High Output Voltage (TRIST <sub>B</sub> , TRIST <sub>(0-2)</sub> , Y <sub>B</sub> )	I <sub>OUT</sub> = -100μA	V <sub>CC</sub> - 0.2v		V
V <sub>OH</sub>	Minimum High Output Voltage (TRIST <sub>B</sub> , TRIST <sub>(0-2)</sub> , LSP_ACTIVE <sub>(0-2)</sub> )	I <sub>OUT</sub> = -12mA. All Outputs Loaded	2.4		V
V <sub>OL</sub>	Maximum Low Output Voltage (TDO <sub>B</sub> , TCK <sub>(0-2)</sub> , TMS <sub>(0-2)</sub> , TDO <sub>(0-2)</sub> , Y <sub>(0-1)</sub> )	$I_{OUT} = +100 \ \mu\text{A}, \ V_{IN}$ (TDI <sub>B</sub> , TMS <sub>B</sub> , TCK <sub>B</sub> ) = V <sub>IL</sub>		0.2	V
V <sub>OL</sub>	$\begin{array}{c} \mbox{Maximum Low Output Voltage} \\ (TDO_{B}, TCK_{(0-2)}, TMS_{(0-2)}, TDO_{(0-2)}, Y_{(0-1)}, Y_{B}, \\ \hline TRST_{(0-2)}) \end{array}$	$I_{OUT}$ = +24 mA, V <sub>IN</sub> on S <sub>(0-6)</sub> and TDI <sub>(0-2)</sub> = V <sub>IH</sub> , V <sub>IL</sub> , All Outputs Loaded		0.55	V
V <sub>OL</sub>	Maximum Low Output Voltage (TRIST <sub>B</sub> , TRIST <sub>(0-2)</sub> , Y <sub>B</sub> )	I <sub>OUT</sub> = +100 μA		0.2	V

# **AC Electrical Characteristics** Over recommended operating supply voltage and temperature ranges unless otherwise specified. Symbol Parameter Т

Symbol	Parameter	Conditions	Тур	Max	Units
t <sub>PHL1</sub> ,	Propagation Delay		8.0	12.0	ns
t <sub>PLH1</sub>	TCK <sub>B</sub> to TCK <sub>(0-2)</sub>				
t <sub>PHL2</sub> ,	Propagation Delay		11.5	16.0	ns
t <sub>PLH2</sub>	TCK <sub>B</sub> to TDO <sub>(0-2)</sub>				
t <sub>PLH3</sub>	Propagation Delay		13.5	19.0	ns
	TRST <sub>B</sub> to TMS <sub>(0-2)</sub>				
t <sub>PHL4</sub>	Propagation Delay		13.0	19.0	ns
	$\overline{\text{TRST}}_{\text{B}}$ to $\overline{\text{TRST}}_{(0-2)}$				
t <sub>PHL5</sub> ,	Propagation Delay		10.5	15.0	ns
t <sub>PLH5</sub>	TCK <sub>B</sub> to TDO <sub>B</sub>				
t <sub>PHL6</sub> ,	Propagation Delay		5.0	9.0	ns
t <sub>PLH6</sub>	$A_{B}$ to $Y_{(0-1)}$				
t <sub>PHL7</sub> ,	Propagation Delay		6.5	10.0	ns
t <sub>PLH7</sub>	A <sub>(0-1)</sub> to Y <sub>B</sub>				
t <sub>PHL8</sub> ,	Propagation Delay		13.0	19.0	ns
t <sub>PLH8</sub>	TCK <sub>B</sub> to LSP_ACTIVE <sub>(0-2)</sub>				
t <sub>PZL9</sub> ,	Enable Time		12.0	17.0	ns
t <sub>PZH9</sub>	TCK <sub>B</sub> to TDO <sub>(0-2)</sub>				
t <sub>PLZ10</sub> ,	Disable Time		11.5	16.0	ns
t <sub>PHZ10</sub>	TCK <sub>B</sub> to TDO <sub>(0-2)</sub>				
t <sub>PHL11</sub> ,	Propagation Delay		11.5	17.0	ns
t <sub>PLH11</sub>	TCK <sub>B</sub> to TRIST <sub>(0-2)</sub>				
t <sub>PZL12</sub> ,	Enable Time		12.5	17.0	ns
t <sub>PZH12</sub>	TCK <sub>B</sub> to TDO <sub>B</sub>				
t <sub>PLZ13</sub> ,	Disable Time		12.5	17.0	ns
t <sub>PHZ13</sub>	TCK <sub>B</sub> to TDO <sub>B</sub>				
t <sub>PHL14</sub> ,	Propagation Delay		12.5	18.0	ns
t <sub>PLH14</sub>	TCK <sub>B</sub> to TRIST <sub>B</sub>				

# Over recommended operating supply voltage and temperature ranges unless otherwise specified

Symbol	Parameter	Conditions	Min	Max	Units
V <sub>OL</sub>	Maximum Low Output Voltage	I <sub>OUT</sub> = +12 mA		0.4	V
	(TRIST <sub>B</sub> , TRIST <sub>(0-2)</sub> , LSP_ACTIVE <sub>(0-2)</sub> )	All Outputs Loaded			
I <sub>IN</sub>	Maximum Input Leakage Current	$V_{IN} = V_{CC}$ or GND		±5.0	μA
	(TCK <sub>B</sub> , S <sub>(0-6)</sub> )				
I <sub>CCT</sub>	Maximum I <sub>CC</sub> /Input	$V_{\rm IN} = V_{\rm CC} - 0.6V$		250	μA
I <sub>cc</sub>	Maximum Quiescent Supply Current	TDI <sub>B</sub> , TMS <sub>B</sub> , TRST <sub>B</sub> ,		1.65	mA
		$\text{TDI}_{(0-2)} = \text{V}_{\text{CC}} \text{ or GND}$			
I <sub>CCD</sub>	Maximum Dynamic Supply Current			130	mA
IOFF	Power Off Leakage Current	$V_{CC} = GND, V_{IN} = 3.6V$		±5.0	μA
	TDO <sub>B</sub> , TCK <sub>(0-2)</sub> , TMS <sub>(0-2)</sub> , TDO <sub>(0-2)</sub> , TRST <sub>(0-2)</sub>				
I <sub>ILR</sub>	TDI <sub>(0-2)</sub> , TDI <sub>B</sub> , OE, TRST <sub>B</sub> , A <sub>(0-1)</sub> , A <sub>B</sub> , TMS <sub>B</sub>	V <sub>IN</sub> = GND	-45	-180	μA
I <sub>IH</sub>	$TDI_{(0-2)}, TDI_{B}, \overline{OE}, \overline{TRST}_{B}, A_{(0-1)}, A_{B}, TMS_{B}$	$V_{IN} = V_{CC}$		+5.0	μA
I <sub>oz</sub>	Maximum TRI-STATE Leakage Current	$V_{IN}$ ( $\overline{OE}$ ) = $V_{IH}$ , $V_{IN}$		±5.0	μA
		$(\overline{\text{TRST}}_{\text{B}}) = V_{\text{IL}}, V_{\text{O}} = V_{\text{CC}},$			
		GND			

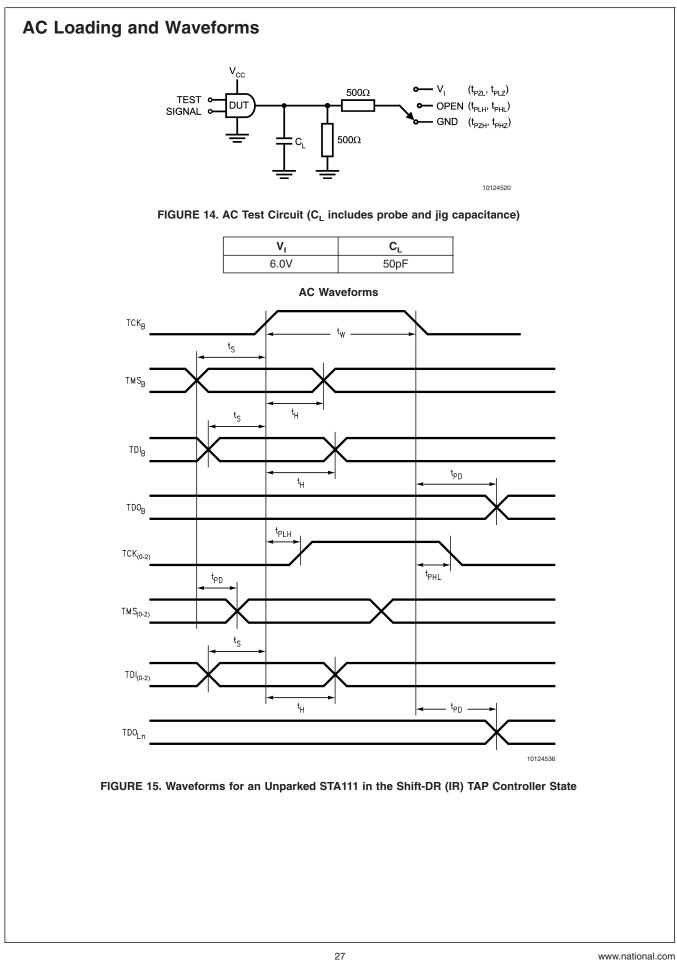
t <sub>PHL1</sub> ,	Propagation Delay	8.0	12.0	ns
t <sub>PLH1</sub>	TCK <sub>B</sub> to TCK <sub>(0-2)</sub>			
t <sub>PHL2</sub> ,	Propagation Delay	11.5	16.0	ns
t <sub>PLH2</sub>	TCK <sub>B</sub> to TDO <sub>(0-2)</sub>			
t <sub>PLH3</sub>	Propagation Delay	13.5	19.0	ns
	TRST <sub>B</sub> to TMS <sub>(0-2)</sub>			
t <sub>PHL4</sub>	Propagation Delay	13.0	19.0	ns
	TRST <sub>B</sub> to TRST <sub>(0-2)</sub>			
t <sub>PHL5</sub> ,	Propagation Delay	10.5	15.0	ns
t <sub>PLH5</sub>	TCK <sub>B</sub> to TDO <sub>B</sub>			
t <sub>PHL6</sub> ,	Propagation Delay	5.0	9.0	ns
t <sub>PLH6</sub>	A <sub>B</sub> to Y <sub>(0-1)</sub>			
t <sub>PHL7</sub> ,	Propagation Delay	6.5	10.0	ns
t <sub>PLH7</sub>	A <sub>(0-1)</sub> to Y <sub>B</sub>			
t <sub>PHL8</sub> ,	Propagation Delay	13.0	19.0	ns
t <sub>PLH8</sub>	TCK <sub>B</sub> to LSP_ACTIVE <sub>(0-2)</sub>			
t <sub>PZL9</sub> ,	Enable Time	12.0	17.0	ns
t <sub>PZH9</sub>	TCK <sub>B</sub> to TDO <sub>(0-2)</sub>			
t <sub>PLZ10</sub> ,	Disable Time	11.5	16.0	ns
t <sub>PHZ10</sub>	TCK <sub>B</sub> to TDO <sub>(0-2)</sub>			
t <sub>PHL11</sub> ,	Propagation Delay	11.5	17.0	ns
t <sub>PLH11</sub>	TCK <sub>B</sub> to TRIST <sub>(0-2)</sub>			
t <sub>PZL12</sub> ,	Enable Time	12.5	17.0	ns
t <sub>PZH12</sub>	TCK <sub>B</sub> to TDO <sub>B</sub>			
t <sub>PLZ13</sub> ,	Disable Time	12.5	17.0	ns
t <sub>PHZ13</sub>	TCK <sub>B</sub> to TDO <sub>B</sub>			
t <sub>PHL14</sub> ,	Propagation Delay	12.5	18.0	ns
		1		1

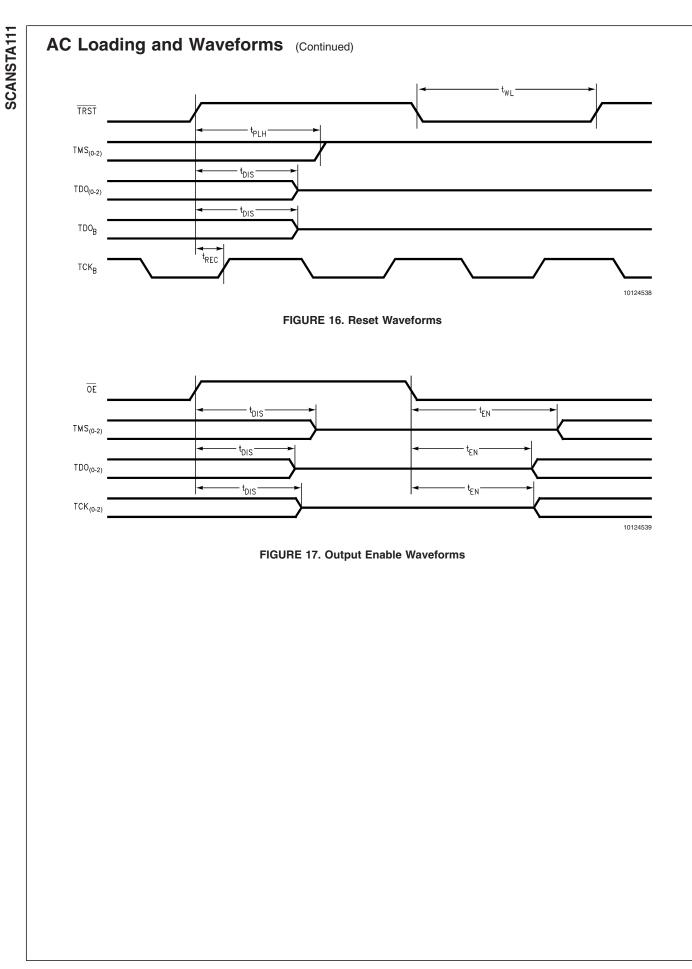
Symbol	Parameter	Conditions	Тур	Max	Units
t <sub>PHL15</sub> ,	Propagation Delay		7.0	11.0	ns
t <sub>PLH15</sub>	TMS <sub>B</sub> to TMS <sub>(0-2)</sub>				
t <sub>PHL16</sub> ,	Propagation Delay		7.0	11.0	ns
t <sub>PLH16</sub>	TDI <sub>B</sub> to TDO <sub>(0-2)</sub>				
t <sub>PZL17</sub> ,	Enable Time		7.5	11.0	ns
t <sub>PZH17</sub>	OE to TMS <sub>(0-2)</sub>				
t <sub>PLZ17</sub> ,	Disable Time		5.0	10.0	ns
t <sub>PHZ17</sub>	OE to TMS <sub>(0-2)</sub>				
t <sub>PZL18</sub> ,	Enable Time		8.0	11.0	ns
t <sub>PZH18</sub>	$\overline{OE}$ to $\overline{TRST}_{(0-2)}$				
t <sub>PLZ18</sub> ,	Disable Time		6.5	10.0	ns
t <sub>PHZ18</sub>	$\overline{OE}$ to $\overline{TRST}_{(0-2)}$				
t <sub>PZL19</sub> ,	Enable Time		8.5	12.0	ns
t <sub>PZH19</sub>	OE to TDO <sub>(0-2)</sub>				
t <sub>PLZ19</sub> ,	Disable Time		7.5	12.0	ns
t <sub>PHZ19</sub>	OE to TDO <sub>(0-2)</sub>				
t <sub>PHL20</sub> ,	Propagation Delay		8.0	13.0	ns
t <sub>PLH20</sub>	$\overline{OE}$ to TRIST <sub>(0-2)</sub>				
t <sub>PZL21</sub> ,	Enable Time		7.5	11.0	ns
t <sub>PZH21</sub>	$\overline{OE}$ to $TCK_{(0-2)}$				
t <sub>PLZ21</sub> ,	Disable Time		6.5	10.0	ns
t <sub>PHZ21</sub>	$\overline{OE}$ to TCK <sub>(0-2)</sub>				

# **AC Electrical Characteristics**

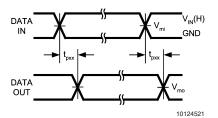
Over recommended operating supply voltage and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Units
ts	Setup Time		2.0	ns
	TMS <sub>B</sub> to TCK <sub>B</sub> ↑			
t <sub>H</sub>	Hold Time		1.0	ns
	TMS <sub>B</sub> to TCK <sub>B</sub> ↑			
s	Setup Time		2.0	ns
	TDI <sub>B</sub> to TCK <sub>B</sub> ↑			
t <sub>H</sub>	Hold Time		1.0	ns
	TDI <sub>B</sub> to TCK <sub>B</sub> ↑			
t <sub>s</sub>	Setup Time		1.5	ns
	TDI <sub>(0-2)</sub> to TCK <sub>B</sub> ↑			
t <sub>H</sub>	Hold Time		1.5	ns
	TDI <sub>(0-2)</sub> to TCK <sub>B</sub> ↑			
tw	Clock Pulse Width		10.0	ns
	TCK <sub>B</sub> (H or L)			
t <sub>WL</sub>	Reset Pulse Width		2.5	ns
	TRST <sub>B</sub> (L)			
t <sub>REC</sub>	Recovery Time		2.0	ns
	TCK <sub>B</sub> ↑ from TRST <sub>B</sub>			
F <sub>MAX</sub>	Maximum Clock Frequency		25.0	MHz

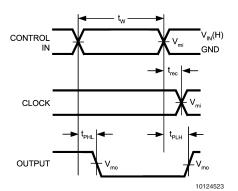


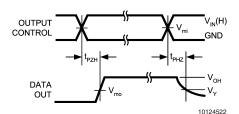


# AC Loading and Waveforms (Continued)

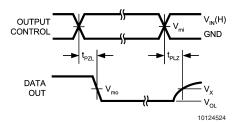


Waveform for Inverting and Non-inverting Functions





Tristate Output High Enable and Disable Times for Logic



Tristate Output Low Enable and Disable Times for Logic

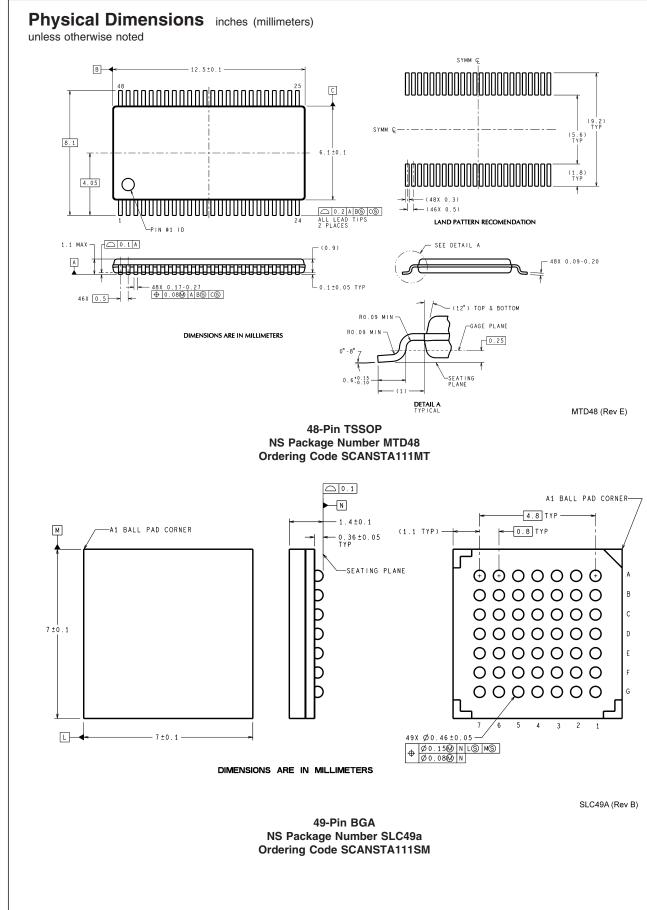
Propagation Delay, Pulse Width and t<sub>REC</sub> Waveforms

FIGURE 18. Timing Waveforms (Input Characteristics; f = 1MHz,  $t_r = t_f = 2.5ns$ )

Symbol	V <sub>cc</sub>		
Symbol	2.7 - 3.6V		
V <sub>IN</sub> (H)	2.7V		
V <sub>mi</sub>	1.5V		
V <sub>mo</sub>	1.5V		
V <sub>x</sub>	V <sub>OL</sub> + 0.3V		
Vy	V <sub>OH</sub> - 0.3V		

# Capacitance & I/O Characteristics

Refer to National's website for IBIS models at http://www.national.com/scan



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SCANSTA111

# Notes

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